NISSHINBO

RP122x Series

400 mA Low Noise and Low Supply Current LDO Regulator

No.EA-403-240812

OVERVIEW

The RP122x is an LDO regulator that provides low output noise, high ripple rejection and fast response characteristics, achieved by low supply current. This device is suitable not only for noise-sensitive applications such as high-performance analog circuits, but also for various applications.

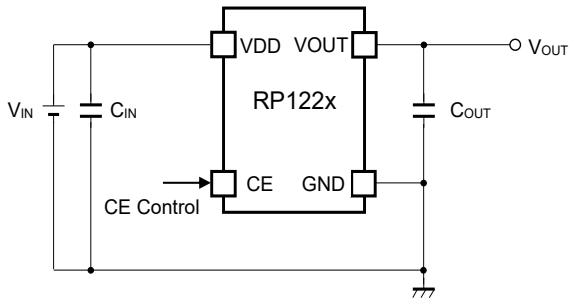
KEY BENEFITS

- Achieves Low Noise, High PSRR and Fast Response.
- Provides Saving Space by Adopting of 4-pin Small Package without Noise Bypass Capacitor.
- Provides Long-Duration of Operation for Battery-powered Equipment by Low Supply Current of 9.5 µA (Typ.), despite the low-noise LDO.

KEY SPECIFICATIONS

- Input Voltage Range (Max.Rating): 1.9 V to 5.5 V (6.0 V)
- Output Voltage Range: 1.2 V to 4.8 V (0.1 V step)
- Output Voltage Accuracy: ±0.8% (V_{SET} ≥ 1.8 V, Ta = 25°C)
- Supply Current: Typ. 9.5 µA
- Output Noise: Typ. 8 µVrms (I_{OUT} = 250 mA)
- Ripple Rejection: Typ. 90 dB (f = 1kHz)
  Typ. 85 dB (f = 10kHz)
  Typ. 65 dB (f = 100kHz)
- Dropout Voltage: Typ. 0.145 V (I_{OUT} = 400 mA, V_{SET} = 2.8 V, RP122Z)
  Typ. 0.170 V (I_{OUT} = 400 mA, V_{SET} = 2.8 V, RP122K/N)
- Protection Features: Thermal Shutdown Protection (Detection Temp. Typ.165°C)
  Inrush Current Limit at Typ.250mA for appr.700µs period after startup
- Ceramic Capacitor (C_{IN}, C_{OUT}): 1.0 µF or more (No Need of Noise Bypass Capacitor)

TYPICAL APPLICATIONS



Without a bypass capacitor for noise

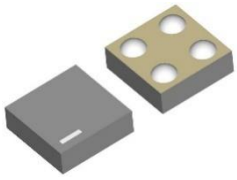
APPLICATIONS

- Mobile Phones and Tablets, Digital Cameras, Audio Devices, and Battery-powered Equipment
- RF Modules
- Clock Generator: VCO, PLL, etc.
- Noise-sensitive Devices: ADC, DAC

PACKAGE



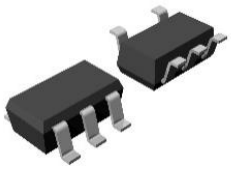
WLCSP-4-P8
0.64 x 0.64 x 0.36 (mm)



WLCSP-4-P12
0.64 x 0.64 x 0.26 (mm)



DFN(PL)1010-4B
1.00 x 1.00 x 0.6 (mm)



SOT-23-5
2.9 x 2.8 x 1.1 (mm)

SELECTION GUIDE

The set output voltage and the auto-discharge function(1) are user-selectable.

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
RP122Zxx1∗-TR-F	WLCSP-4-P8	5,000 pcs	Yes	Yes
RP122Zxx3∗-TR-F	WLCSP-4-P12	10,000 pcs	Yes	Yes
RP122Kxx1∗-TR	DFN(PL)1010-4B	10,000 pcs	Yes	Yes
RP122Nxx1∗-TR-FE	SOT-23-5	3,000 pcs	Yes	Yes
RP122Zxx1∗-TR-T	WLCSP-4-P8	5,000 pcs	Yes	Yes
RP122Zxx4∗-TR-T	WLCSP-4-P12	10,000 pcs	Yes	Yes
RP122Kxx1∗-TR-V	DFN(PL)1010-4B	10,000 pcs	Yes	Yes
RP122Nxx1∗-TR-FV	SOT-23-5	3,000 pcs	Yes	Yes

xx: Specify the set output voltage (V_{SET}) within the range of 1.2 V to 4.8 V in 0.1 V steps.

The voltage in 0.05 V step is shown as follows.

Ex. 1.85 V: RP122x18x∗5

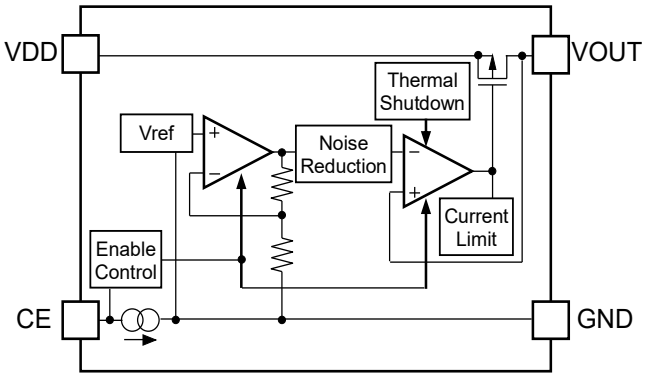
∗ : Specify whether with the auto-discharge or not.

B: without the auto-discharge function

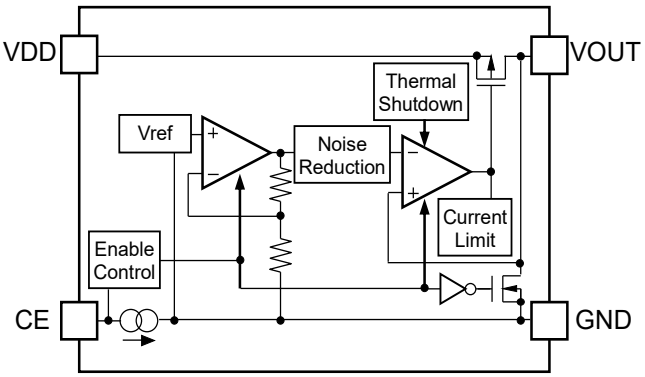
D: with the auto-discharge function

RP122Kxx1x-TR-V, RP122Nxx1x-TR-FV are developing products.

BLOCK DIAGRAMS



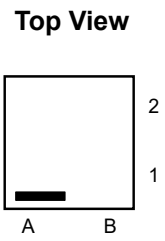
RP122xxxxB Block Diagram

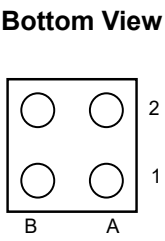


RP122xxxxD Block Diagram

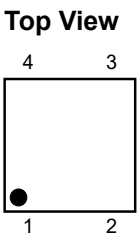
(1) Auto-discharge function quickly lowers the output voltage to 0 V, when the chip enable signal is switched from the active mode to the standby mode, by releasing the electrical charge accumulated in the external capacitor.

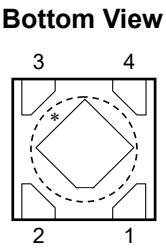
PIN DESCRIPTIONS



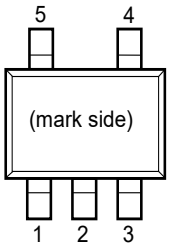


RP122Z (WLCSP-4-P8 / WLCSP-4-P12) Pin Configuration





RP122K (DFN (PL) 1010-4B) Pin Configuration



RP122N (SOT-23-5) Pin Configuration

RP122Zxx1x(WLCSP-4-P8), RP122Zxx3x(WLCSP-4-P12), RP122Zxx4x(WLCSP-4-P12) Pin Description

Pin No.	Symbol	Description
A1	VDD	Input Pin
A2	VOUT	Output Pin
B1	CE	Chip Enable Pin, Active-high
B2	GND	Ground Pin

RP122K Pin Description

Pin No.	Symbol	Description
1	VOUT	Output Pin
2	GND	Ground Pin
3	CE	Chip Enable Pin, Active-high
4	VDD	Input Pin

∗ The tab on the bottom of the package must be electrically connected to GND (substrate level) when mounted on the board.

RP122N Pin Description

Pin No.	Symbol	Description
1	VDD	Input Pin
2	GND	Ground Pin
3	CE	Chip Enable Pin, Active-high
4	NC	No Connection
5	VOUT	Output Pin

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating	Unit
V_{IN}	Input Voltage	−0.3 to 6.0	V
V_{CE}	Input Voltage (CE pin)	−0.3 to 6.0	V
V_{OUT}	Output Voltage	−0.3 to V_{IN} + 0.3	V
I_{OUT}	Output Current	600	mA
P_D	Power Dissipation	Refer to Appendix "*POWER DISSIPATION*"	
Tj	Junction Temperature Range	−40 to 125	°C
Tstg	Storage Temperature Range	−55 to 125	°C

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause permanent damage and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings are not assured.

RECOMMENDED OPERATING CONDITIONS

Symbol	Item	Rating	Unit
V_{IN}	Input Voltage	1.9 to 5.5	V
Ta	Operating Temperature Range	−40 to 85	°C

RECOMMENDED OPERATING CONDITIONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if they are used over such ratings by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

ELECTRICAL CHARACTERISTICS

V_{IN} = V_{SET} + 1 V (V_{IN} = 5.5 V when V_{SET} ≥ 4.5 V), I_{OUT} = 1mA, C_{IN} = C_{OUT} = 1µF, unless otherwise specified.
The specifications surrounded by [ ] are guaranteed by design engineering at -40°C ≤ Ta ≤ 85°C.

RP122xxxxx Electrical Characteristics (Ta = 25°C)

Symbol	Parameter		Conditions		Min.	Typ.	Max.	Unit
V_{OUT}	Output Voltage		Ta = 25°C	V_{SET} ≥ 1.8V	x0.992		x1.008	V
				V_{SET} < 1.8V	−14		+14	mV
			−40°C ≤ Ta ≤ 85°C	V_{SET} ≥ 1.8V	[x0.987]		[x1.012]	V
				V_{SET} < 1.8V	Refer to *PRODUCT-SPECIFIC ELECTRICAL CHARACTERISTICS*			
I_{OUT}	Output Current				400			mA
$\Delta V_{OUT}/\Delta I_{OUT}$	Load Regulation	RP122Z	1 mA ≤ I_{OUT} ≤ 400 mA V_{IN} = V_{SET} + 0.5 V, V_{IN} ≥ 1.9 V			3	[25]	mV
		RP122K/N	1 mA ≤ I_{OUT} ≤ 400 mA			13	[40]	
V_{DIF}	Dropout Voltage		I_{OUT} = 400 mA		Refer to *PRODUCT-SPECIFIC ELECTRICAL CHARACTERISTICS*			
I_{SS}	Supply Current		I_{OUT} = 0 mA			9.5	[25]	µA
$I_{STANDBY}$	Standby Current		V_{CE} = 0 V			0.01	0.3	µA
$\Delta V_{OUT}/\Delta V_{IN}$	Line Regulation		1.2V≤V_{SET}<1.4V	1.9V≤V_{IN}≤5.5V		0.02	[0.10]	%/V
			1.4V≤V_{SET}<4.3V	V_{SET}+0.5V≤V_{IN}≤5.5V				
			4.3V≤V_{SET}≤4.8V	V_{SET}+0.3V≤V_{IN}≤5.5V				
RR	Ripple Rejection		Ripple 0.2 Vp-p, I_{OUT} = 20 mA	f = 1 kHz		90		dB
				f = 10 kHz		85		
				f = 100 kHz		65		
I_{SC}	Short Current Limit		V_{OUT} = 0 V			70		mA
I_{PD}	CE Pull-down Current					0.25	[0.50]	µA
V_{CEH}	CE Input Voltage, high				[1.0]			V
V_{CEL}	CE Input Voltage, low						[0.4]	V
en	Output Noise		BW =10Hz to 100kHz	I_{OUT} = 1 mA		12		µVrms
				I_{OUT} = 250 mA		8		
T_{TSD}	Thermal Shutdown Temperature, detection		Junction Temperature			165		ºC
T_{TSR}	Thermal Shutdown Temperature, released		Junction Temperature			110		ºC
R_{LOW}	Auto-discharge NMOS On-resistance (RP122xxxxD only)		V_{IN} = 5.0 V, CE = 0 V,			50		Ω

All test items listed under Electrical Characteristics are done under the pulse load condition (Tj ≈ Ta = 25°C) except Ripple Rejection and Output Noise.

The specifications surrounded by [ ] are guaranteed by design engineering at - 40°C ≤ Ta ≤ 85°C

RP122xxxxx Product-specific Electrical Characteristics

Product Name	V_{OUT} [V]						V_{DIF} [V]			
	Ta = 25°C			−40°C ≤ Ta ≤ 85°C			RP122Z		RP122K/N	
	Min.	Typ.	Max.	Min.	Typ.	Max.	Typ.	Max.	Typ.	Max.
RP122x12xx	1.186	1.200	1.214	[1.180]	1.200	[1.218]	(1)	(1)	(1)	(1)
RP122x12xx5	1.236	1.250	1.264	[1.230]	1.250	[1.268]	(1)	(1)	(1)	(1)
RP122x13xx	1.286	1.300	1.314	[1.280]	1.300	[1.319]	(1)	(1)	(1)	(1)
RP122x14xx	1.386	1.400	1.414	[1.379]	1.400	[1.419]	(1)	[0.450](2)	(1)	[0.500](2)
RP122x15xx	1.486	1.500	1.514	[1.479]	1.500	[1.519]	(1)	[0.430]	(1)	[0.470]
RP122x16xx	1.586	1.600	1.614	[1.578]	1.600	[1.620]	0.240(2)	[0.385]	0.270(2)	[0.425]
RP122x17xx	1.686	1.700	1.714	[1.678]	1.700	[1.720]	0.235	[0.350]	0.260	[0.390]
RP122x18xx	1.786	1.800	1.814	[1.777]	1.800	[1.821]	0.215	[0.325]	0.240	[0.365]
RP122x18xx5	1.836	1.850	1.864	[1.826]	1.850	[1.872]	0.215	[0.325]	0.240	[0.365]
RP122x19xx	1.885	1.900	1.915	[1.876]	1.900	[1.922]	0.200	[0.305]	0.225	[0.345]
RP122x20xx	1.984	2.000	2.016	[1.974]	2.000	[2.024]	0.190	[0.290]	0.215	[0.330]
RP122x21xx	2.084	2.100	2.116	[2.073]	2.100	[2.125]	0.180	[0.270]	0.205	[0.310]
RP122x22xx	2.183	2.200	2.217	[2.172]	2.200	[2.226]	0.170	[0.260]	0.195	[0.300]
RP122x23xx	2.282	2.300	2.318	[2.271]	2.300	[2.327]	0.170	[0.260]	0.195	[0.300]
RP122x24xx	2.381	2.400	2.419	[2.369]	2.400	[2.428]	0.170	[0.260]	0.195	[0.300]
RP122x25xx	2.480	2.500	2.520	[2.468]	2.500	[2.530]	0.155	[0.240]	0.180	[0.280]
RP122x26xx	2.580	2.600	2.620	[2.567]	2.600	[2.631]	0.155	[0.240]	0.180	[0.280]
RP122x27xx	2.679	2.700	2.721	[2.665]	2.700	[2.732]	0.155	[0.240]	0.180	[0.280]
RP122x28xx	2.778	2.800	2.822	[2.764]	2.800	[2.833]	0.145	[0.225]	0.170	[0.265]
RP122x28xx5	2.828	2.850	2.872	[2.813]	2.850	[2.884]	0.145	[0.225]	0.170	[0.265]
RP122x29xx	2.877	2.900	2.923	[2.863]	2.900	[2.934]	0.145	[0.225]	0.170	[0.265]
RP122x29xx5	2.927	2.950	2.973	[2.912]	2.950	[2.985]	0.145	[0.225]	0.170	[0.265]
RP122x30xx	2.976	3.000	3.024	[2.961]	3.000	[3.036]	0.145	[0.225]	0.170	[0.265]
RP122x30xx5	3.026	3.050	3.074	[3.011]	3.050	[3.086]	0.145	[0.225]	0.170	[0.265]
RP122x31xx	3.076	3.100	3.124	[3.060]	3.100	[3.137]	0.145	[0.225]	0.170	[0.265]
RP122x31xx5	3.125	3.150	3.175	[3.110]	3.150	[3.187]	0.145	[0.225]	0.170	[0.265]
RP122x32xx	3.175	3.200	3.225	[3.159]	3.200	[3.238]	0.145	[0.225]	0.170	[0.265]
RP122x33xx	3.274	3.300	3.326	[3.258]	3.300	[3.339]	0.130	[0.205]	0.155	[0.245]
RP122x34xx	3.373	3.400	3.427	[3.356]	3.400	[3.440]	0.130	[0.205]	0.155	[0.245]
RP122x35xx	3.472	3.500	3.528	[3.455]	3.500	[3.542]	0.130	[0.205]	0.155	[0.245]
RP122K35xx5	3.522	3.550	3.578	[3.504]	3.550	[3.592]	-	-	0.155	[0.245]

(1) Input voltage should be equal or more than the minimum operating voltage of 1.9 V.
(2) When "Output voltage + Dropout Voltage" < 1.9 V, input voltage must be equal or more than the minimum operating voltage of 1.9 V.

The specifications surrounded by [ ] are guaranteed by design engineering at - 40°C ≤ Ta ≤ 85°C

RP122xxxxx Product-specific Electrical Characteristics

Product Name	V_{OUT} [V]						V_{DIF} [V]			
	Ta = 25°C			−40°C ≤ Ta ≤ 85°C			RP122Z		RP122K/N	
	Min.	Typ.	Max.	Min.	Typ.	Max.	Typ.	Max.	Typ.	Max.
RP122x36xx	3.572	3.600	3.628	[3.554]	3.600	[3.643]	0.120	[0.195]	0.145	[0.235]
RP122x37xx	3.671	3.700	3.729	[3.652]	3.700	[3.744]	0.120	[0.195]	0.145	[0.235]
RP122x38xx	3.770	3.800	3.830	[3.751]	3.800	[3.845]	0.120	[0.195]	0.145	[0.235]
RP122x39xx	3.869	3.900	3.931	[3.850]	3.900	[3.946]	0.120	[0.195]	0.145	[0.235]
RP122x40xx	3.968	4.000	4.032	[3.948]	4.000	[4.048]	0.115	[0.185]	0.140	[0.225]
RP122x41xx	4.068	4.100	4.132	[4.047]	4.100	[4.149]	0.115	[0.185]	0.140	[0.225]
RP122x42xx	4.167	4.200	4.233	[4.146]	4.200	[4.250]	0.115	[0.185]	0.140	[0.225]
RP122x42xx5	4.216	4.250	4.284	[4.195]	4.250	[4.301]	0.115	[0.185]	0.140	[0.225]
RP122x43xx	4.266	4.300	4.334	[4.245]	4.300	[4.351]	0.115	[0.185]	0.140	[0.225]
RP122x44xx	4.365	4.400	4.435	[4.343]	4.400	[4.452]	0.115	[0.185]	0.140	[0.225]
RP122x45xx	4.464	4.500	4.536	[4.442]	4.500	[4.554]	0.115	[0.185]	0.140	[0.225]
RP122x45xx5	4.514	4.550	4.586	[4.491]	4.550	[4.604]	0.115	[0.185]	0.140	[0.225]
RP122x46xx	4.564	4.600	4.636	[4.541]	4.600	[4.655]	0.115	[0.185]	0.140	[0.225]
RP122x47xx	4.663	4.700	4.737	[4.639]	4.700	[4.756]	0.115	[0.185]	0.140	[0.225]
RP122x48xx	4.762	4.800	4.838	[4.738]	4.800	[4.857]	0.115	[0.185]	0.140	[0.225]

THEORY OF OPERATION

Inrush Current Limit

The inrush current limit value at start-up increases in proportion to the capacitance of C_{OUT}. If not flow the load current (I_{LOAD}) except the charge current to C_{OUT}, the inrush current reaches 250mA when the effective capacitance of C_{OUT} becomes appr.6.0 µF or more, and the inrush current limit protection runs. During appr.700 µs after the CE pin becomes "H", the inrush current, which occurs at charging the capacitor of C_{OUT}, is limited at appr.250 mA. The power-on time (t_{ON}) can be calculated from the following equation. If the capacitance value of C_{OUT} is too much, the time-out occurs and the inrush current increases.

$$t_{ON} = t_D + C_{OUT} \cdot V_{SET} / I_{LIM_START}$$

t_D : Delay Time at Start-up Typ.50 µs
V_{SET} : Set Output Voltage
I_{LIM_START} : Limit Current at Start-up Typ.250 mA

If flow the load current (I_{LOAD}) except the charge current to C_{OUT} during start-up, the start-up time becomes longer. The load current over I_{LIM_START} cannot be applied.

Minimum Operating Voltage

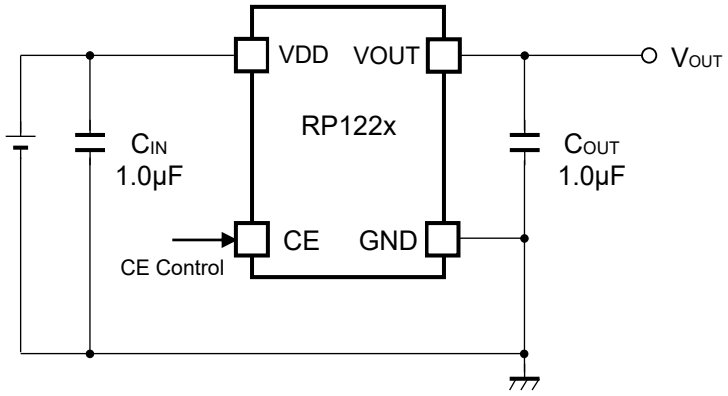
The RP122x does not include an UVLO circuit. To make the internal circuit operate normally and to ensure good output regulation, V_{IN} has to be: $V_{IN} \geq V_{SET} + V_{DIF}$ (Min.1.9 V). To bring out the best characteristics of the output noise voltage, the ripple rejection and the load transient response, V_{IN} has to be $V_{IN} = V_{SET} + 1.0$ V.

Thermal Shutdown Protection

Thermal shutdown deactivates the circuit when the junction temperature exceeds the thermal shutdown threshold (T_{TSD}) of Typ. 165 °C, and reactivates it when the junction temperature falls below the thermal shutdown release threshold (T_{TSR}) of Typ. 110 °C. During the reactivation, the inrush current limit is in operation. Note that deactivation and activation cycle can be repeated due to load, heat dissipation and ambient temperature conditions. Thermal shutdown cannot be used for the purpose of heat sink, so the repetitive cycles of deactivation and activation may affect the reliability of the device.

APPLICATION INFORMATION

Typical Application Circuit



RP122x Typical Application Circuit

Technical Notes Related to External Components

- Ensure the VDD and GND lines are sufficiently robust. If their impedances are too high, noise pickup or unstable operation may result. Connect a 1.0 µF or more input capacitor (C_{IN}) between the VDD and GND pins with shortest-distance wiring. It is recommended to use a ceramic capacitor of 6.3 V and more such as the X7R and the X5R having small temperature dependence to ESR, ESL, and capacitance.
- Phase compensation is provided to secure stable operation even when the load current is varied. For this purpose, use a ceramic capacitor of 1.0 µF or more with ESR (Equivalent Series Resistance) of up to 300 mΩ to connect the output capacitor (C_{OUT}) between the VOUT and GND pins with shortest-distance wiring. Besides, set for the output capacitor to ensure the following effective capacitance in consideration of the dependence of temperature, DC bias, and package size.

Set Output Voltage (V_{SET})	Effective Capacitance
1.2 V ≤ V_{SET} < 2.0 V	0.75 µF and more
2.0 V ≤ V_{SET} < 3.4 V	0.70 µF and more
3.4 V ≤ V_{SET} ≤ 4.8 V	0.60 µF and more

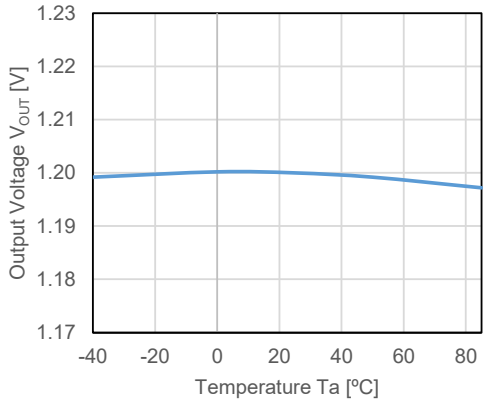
In case of using a tantalum type capacitor with a large ESR, the output might become unstable. Evaluate your circuit including consideration of frequency characteristics with a parallel connection the above ceramic and the tantalum type capacitors.

TYPICAL CHARACTERISTICS

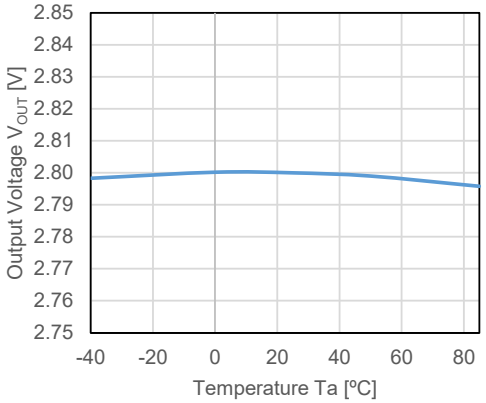
Typical Characteristics are intended to be used as reference data, they are not guaranteed.

1) Output Voltage vs. Temperature (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF)

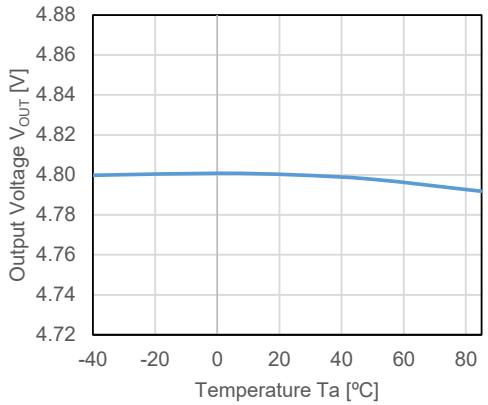
RP122x12xx, V_{IN} = 2.2 V, I_{OUT} = 1 mA



RP122x28xx, V_{IN} = 3.8 V, I_{OUT} = 1 mA

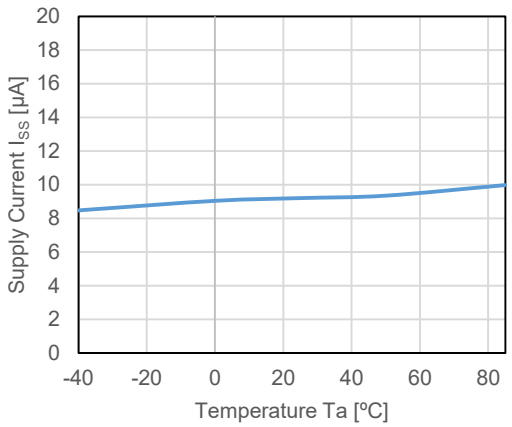


RP122x48xx, V_{IN} = 5.5 V, I_{OUT} = 1 mA

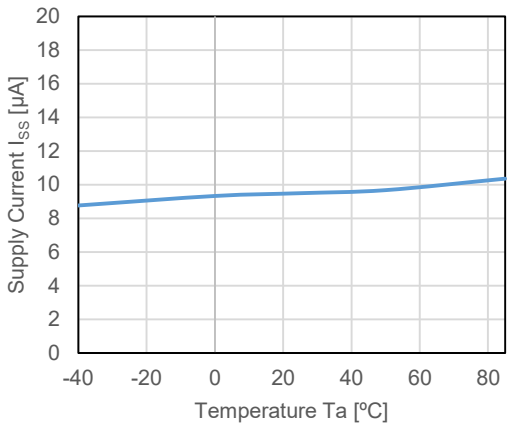


2) Supply Current vs. Temperature (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF)

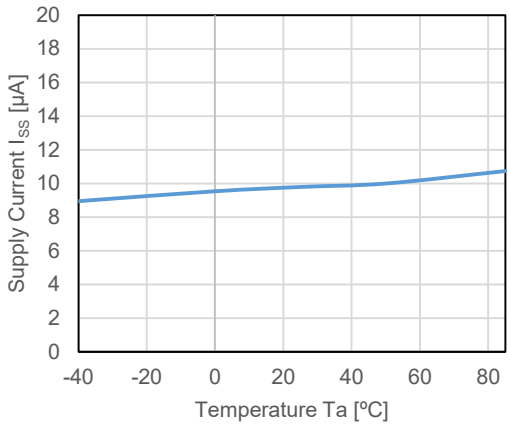
RP122x12xx, V_{IN} = 2.2 V



RP122x28xx, V_{IN} = 3.8 V

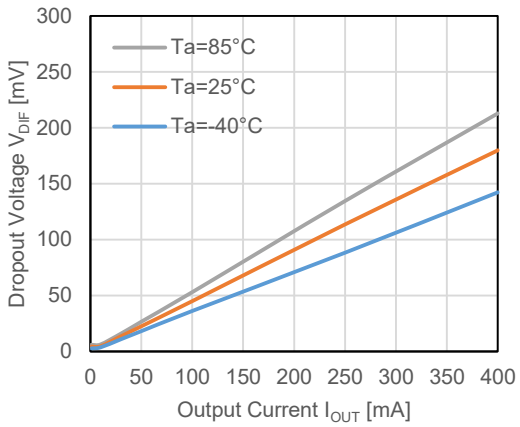


RP122x48xx, V_{IN} = 5.5 V

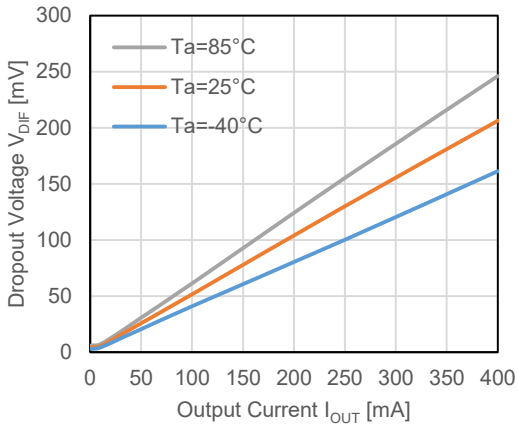


3) Dropout Voltage vs. Output Current (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF)

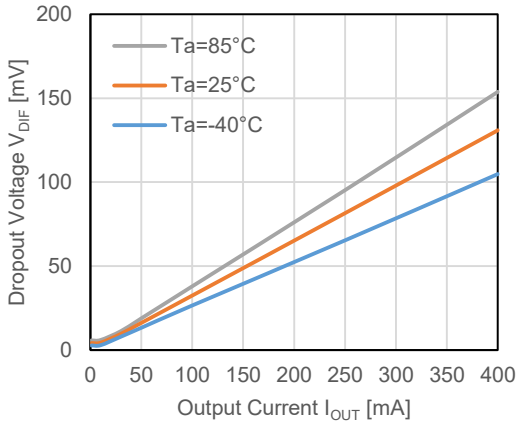
RP122Z18xx



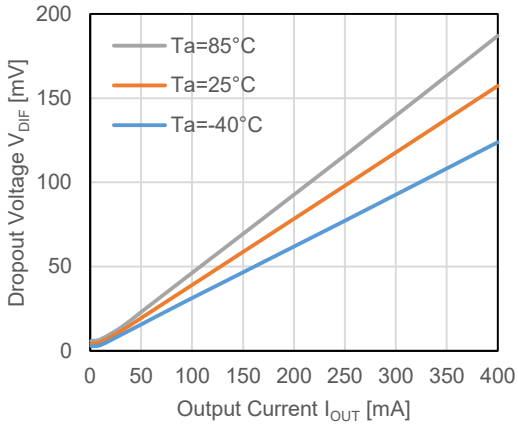
RP122K/N181x



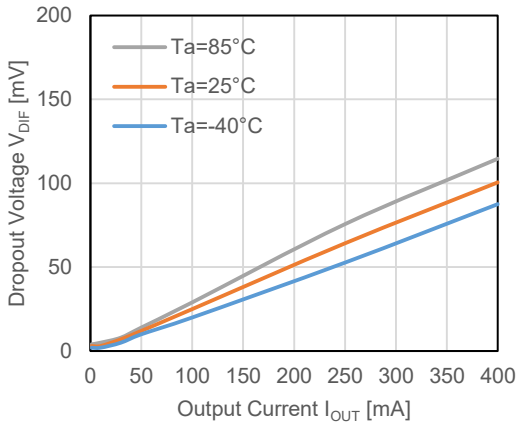
RP122Z28xx



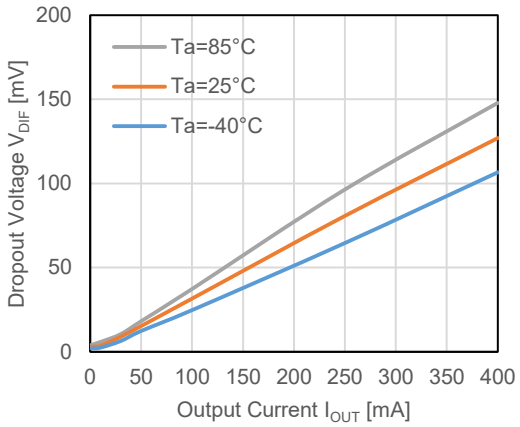
RP122K/N281x



RP122Z48xx

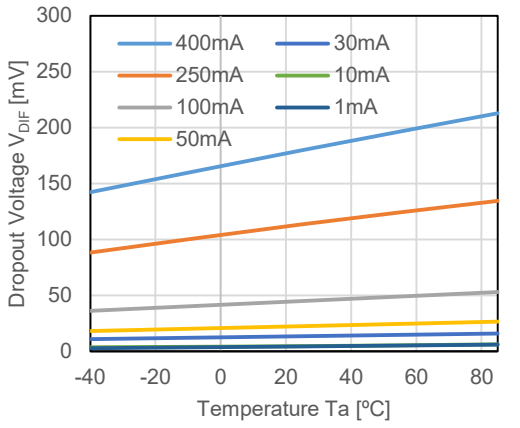


RP122K/N481x

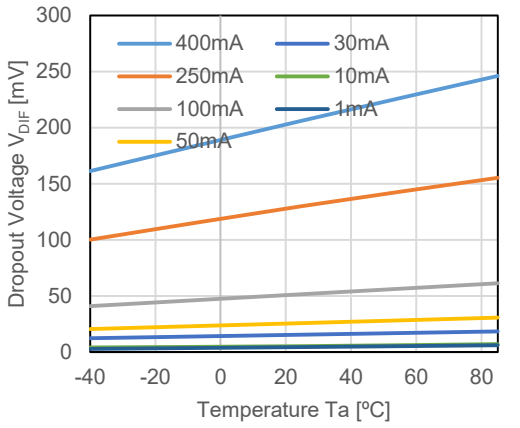


4) Dropout Voltage vs. Temperature (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF)

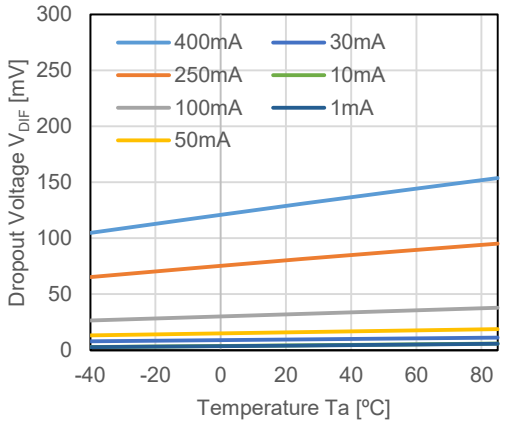
RP122Z18xx



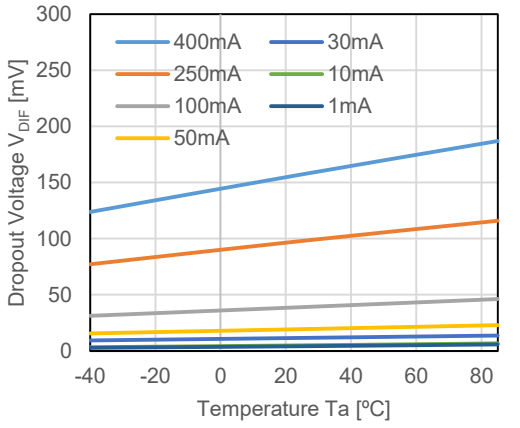
RP122K/N181x



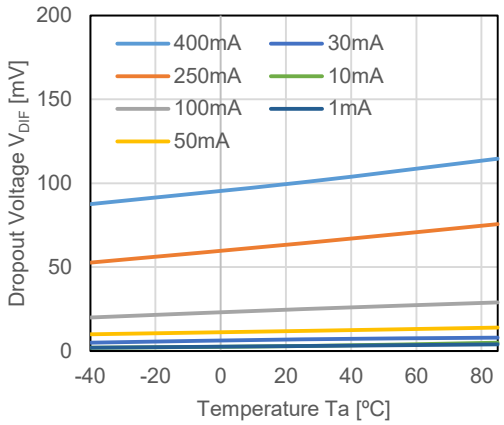
RP122Z28xx



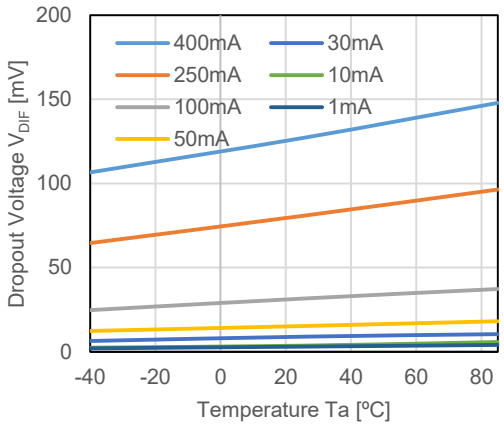
RP122K/N281x



RP122Z48xx

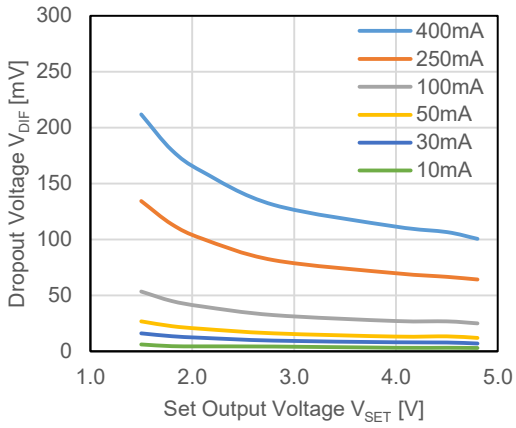


RP122K/N481x

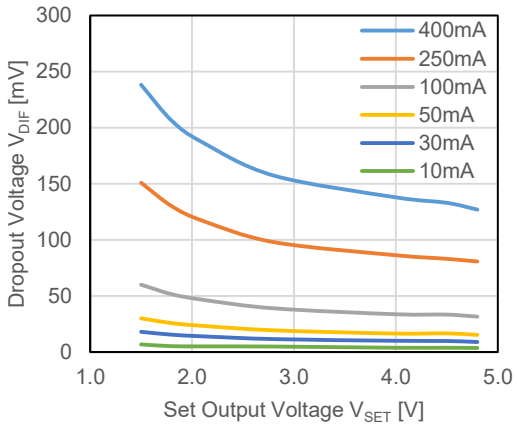


5) Dropout Voltage vs. Set Output Voltage (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF, Ta = 25°C)

RP122Zxxxx

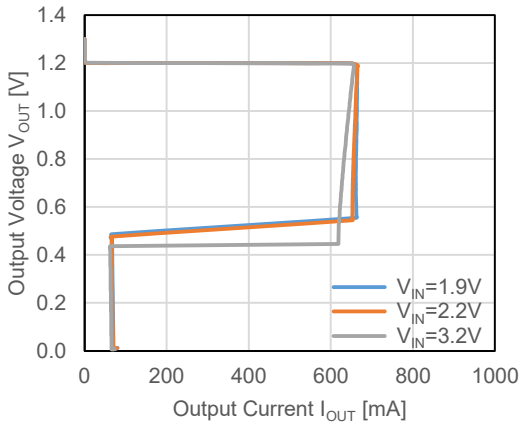


RP122K/Nxx1x

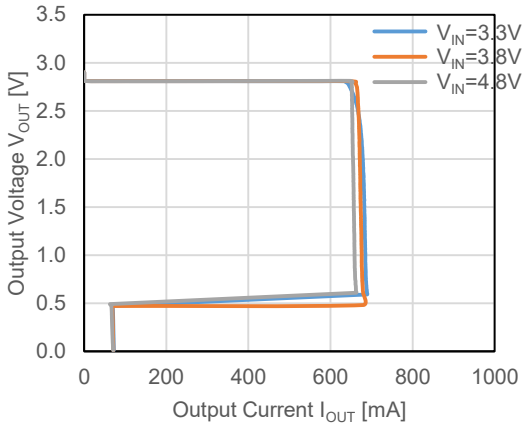


6) Output Voltage vs. Output Current (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF, Ta = 25°C)

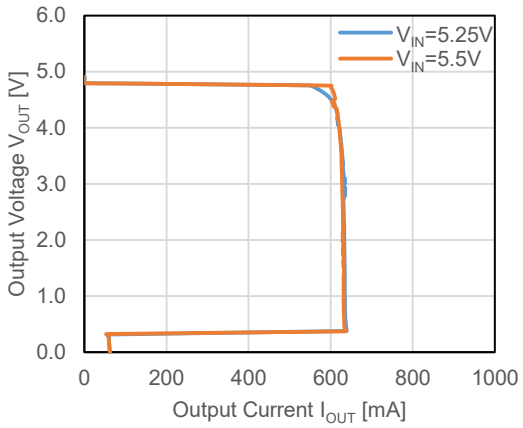
RP122x12xx



RP122x28xx

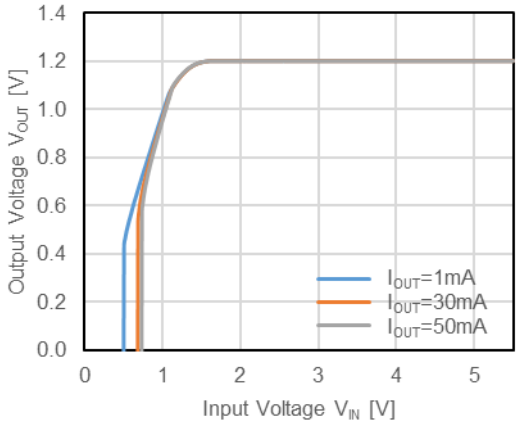


RP122x48xx

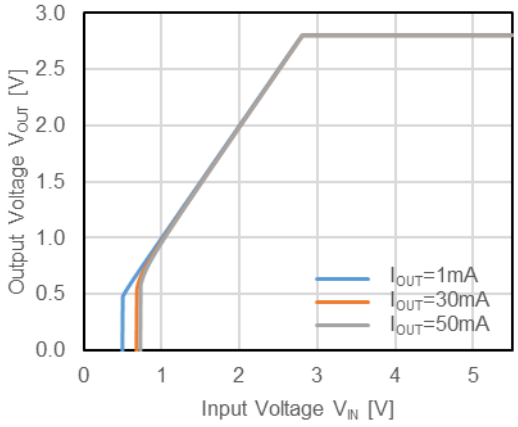


7) Output Voltage vs. Input Voltage (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF, Ta = 25°C)

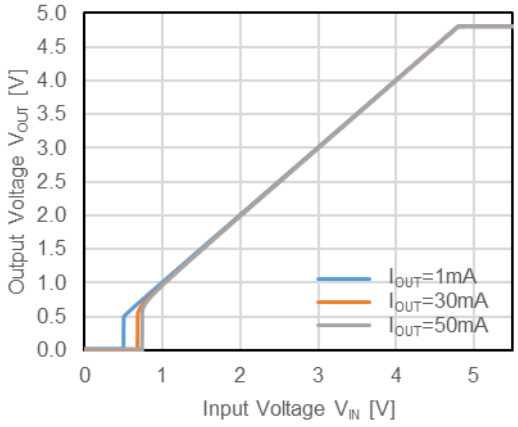
RP122x12xx



RP122x28xx

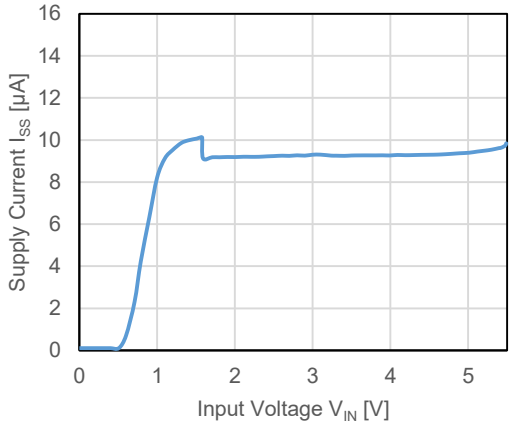


RP122x48xx

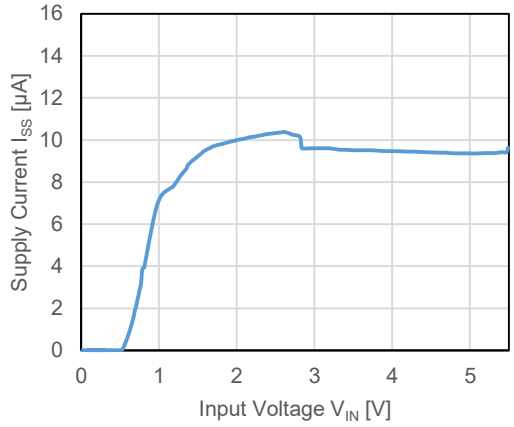


8) Supply Current vs. Input Voltage (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF, Ta = 25°C)

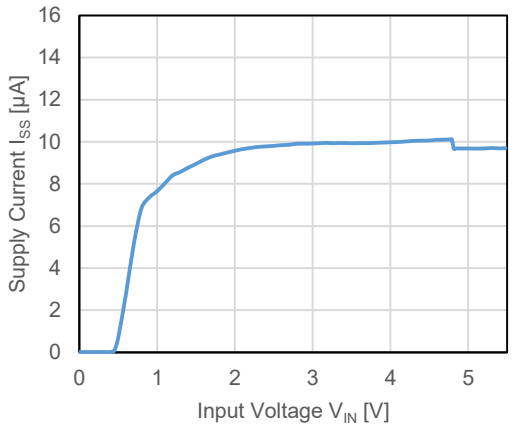
RP122x12xx



RP122x28xx

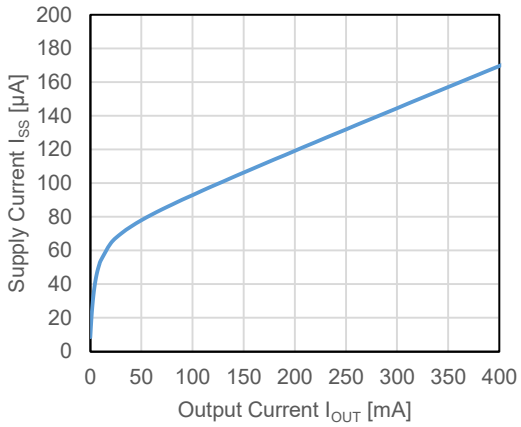


RP122x48xx

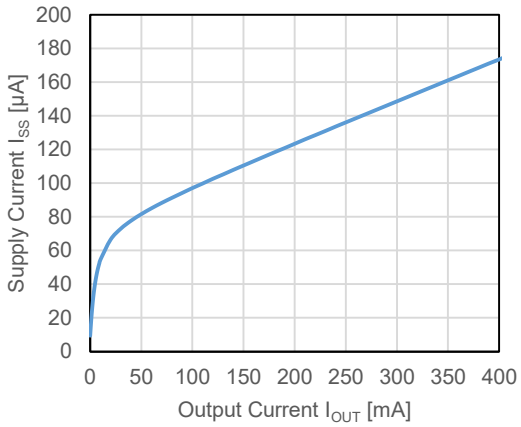


9) Supply Current vs. Output Current (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF, Ta = 25°C)

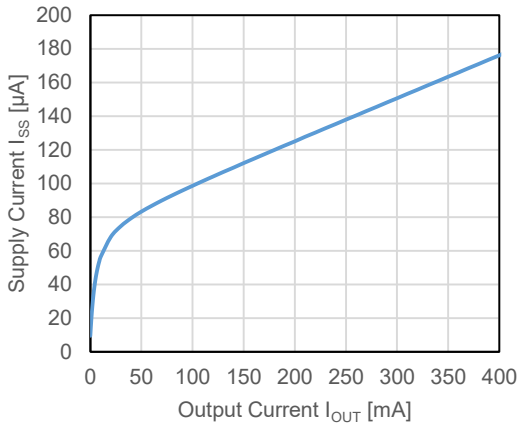
RP122x12xx, V_{IN} = 2.2 V



RP122x28xx, V_{IN} = 3.8 V

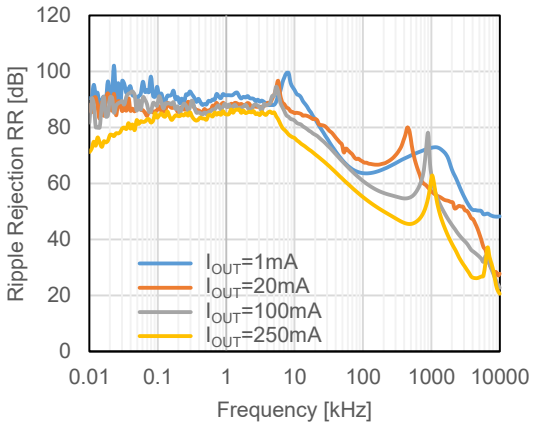


RP122x48xx, V_{IN} = 5.5 V

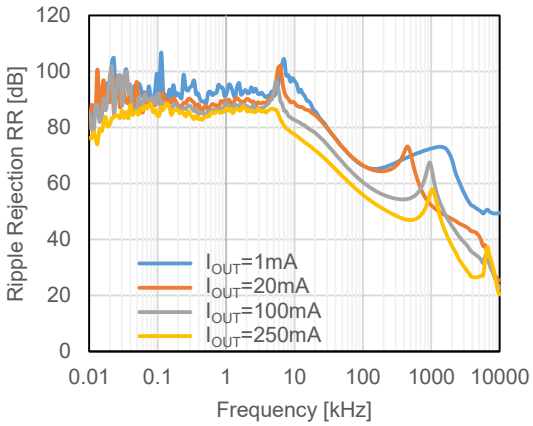


10) Ripple Rejection vs. Frequency (C_{OUT} = Ceramic 1.0 µF, Ripple = 0.2 Vp-p, Ta = 25°C)

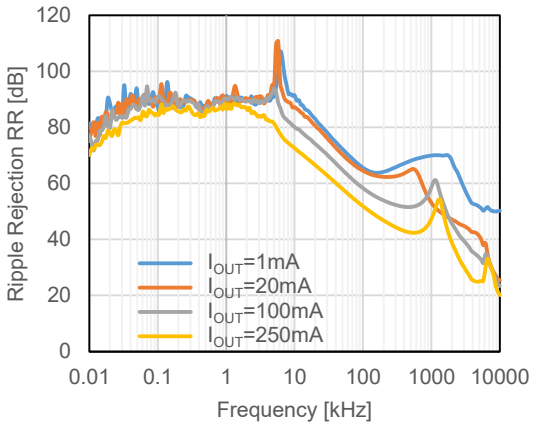
RP122x12xx, V_{IN} = 2.2 V



RP122x28xx, V_{IN} = 3.8 V

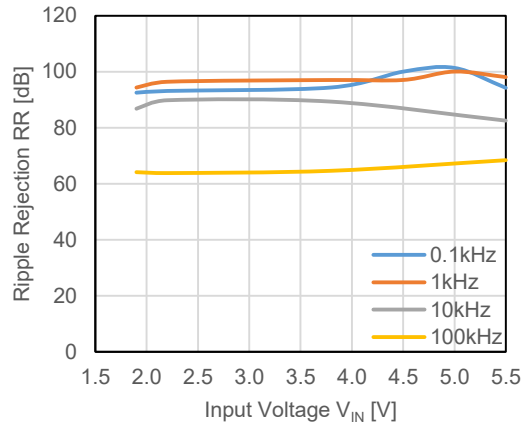


RP122x48xx, V_{IN} = 5.5 V

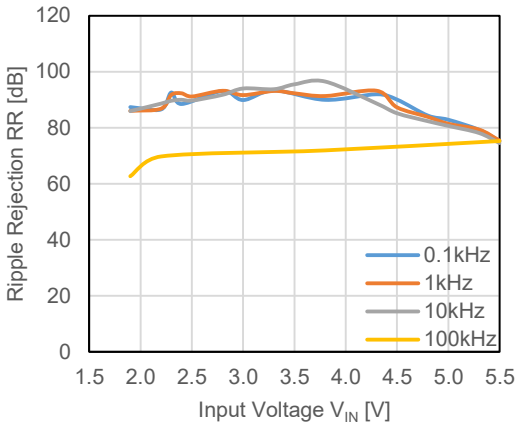


11) Ripple Rejection vs. Input Voltage (C_{OUT} = Ceramic 1.0 µF, Ripple = 0.2 Vp-p, Ta = 25°C)

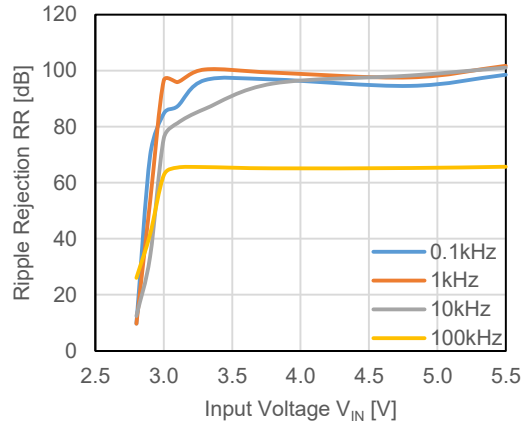
RP122x12xx, I_{OUT} = 1 mA



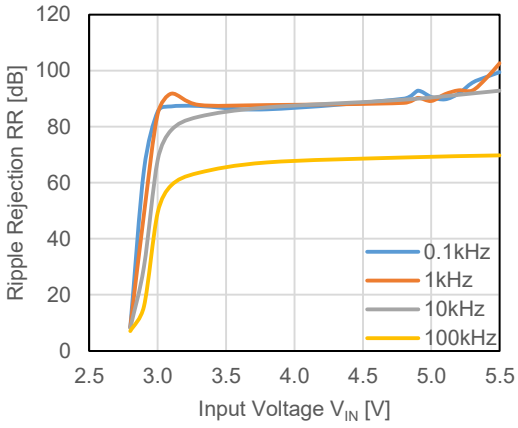
RP122x12xx, I_{OUT} = 20 mA



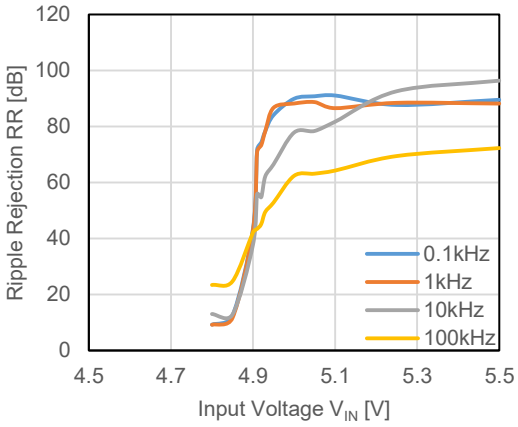
RP122x28xx, I_{OUT} = 1 mA



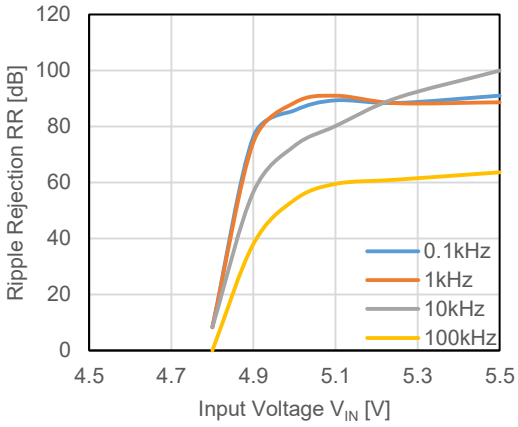
RP122x28xx, I_{OUT} = 20 mA



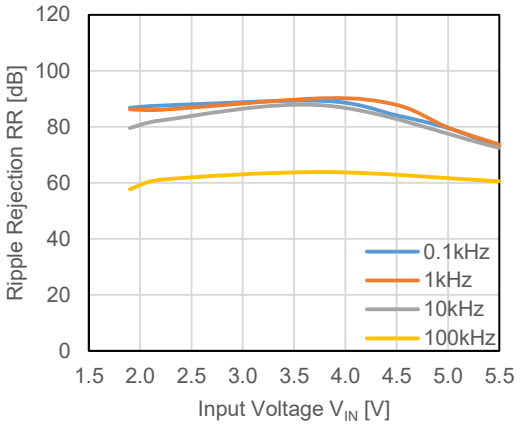
RP122x48xx, I_{OUT} = 1 mA



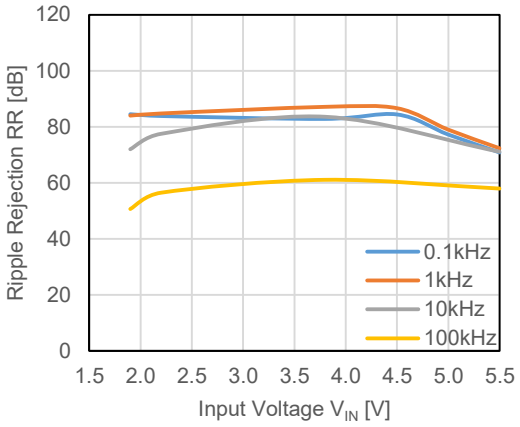
RP122x48xx, I_{OUT} = 20 mA



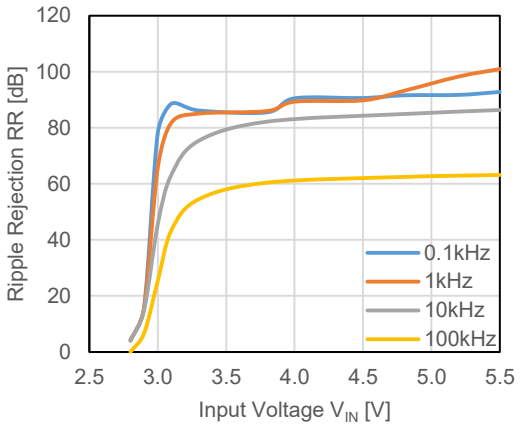
RP122x12xx, I_{OUT} = 100 mA



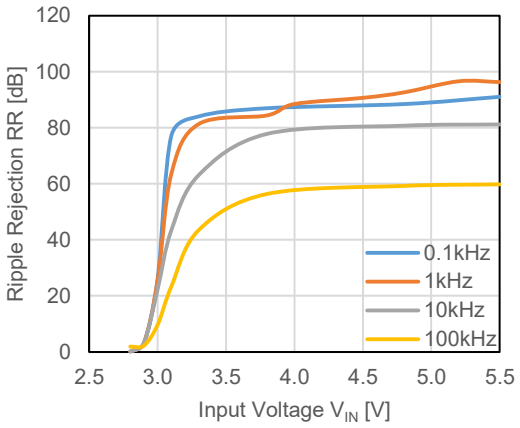
RP122x12xx, I_{OUT} = 250 mA



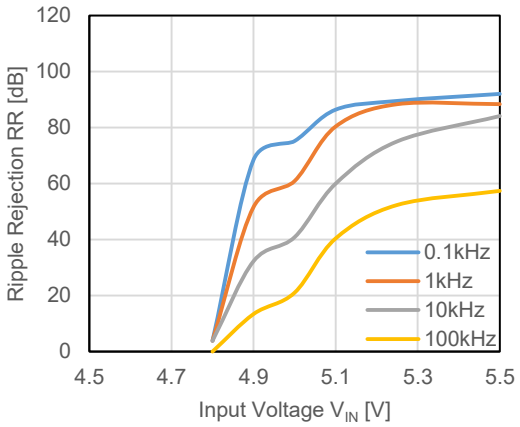
RP122x28xx, I_{OUT} = 100 mA



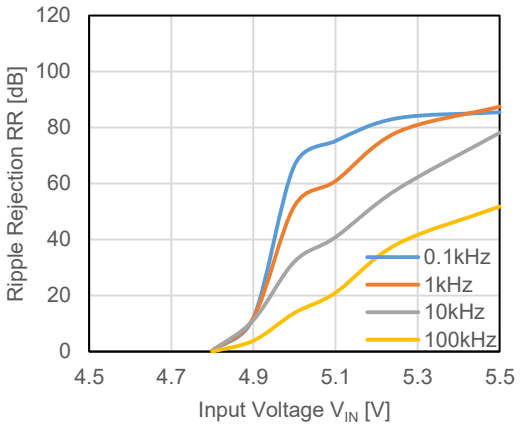
RP122x28xx, I_{OUT} = 250 mA



RP122x48xx, I_{OUT} = 100 mA

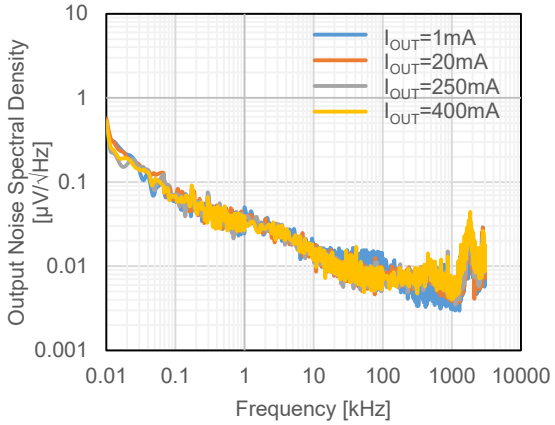


RP122x48xx, I_{OUT} = 250 mA

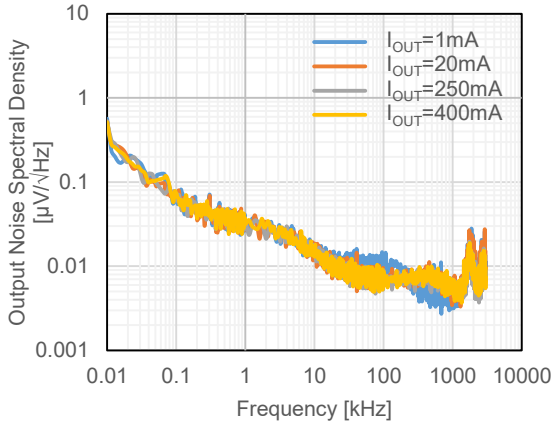


12) Output Noise Spectral Density vs. Frequency (C_{IN}=Ceramic 1.0µF, C_{OUT}=Ceramic 1.0µF, Ta=25°C)

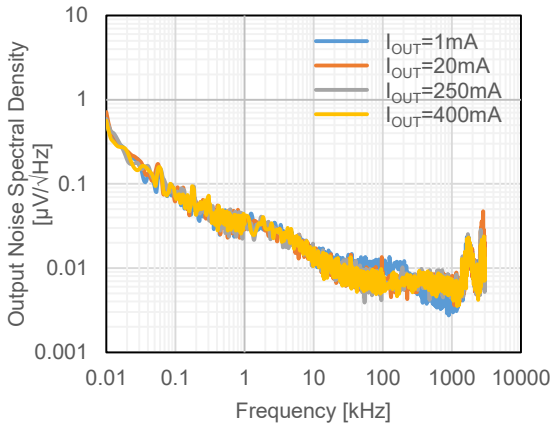
RP122x12xx, V_{IN} = 2.2 V



RP122x28xx, V_{IN} = 3.8 V

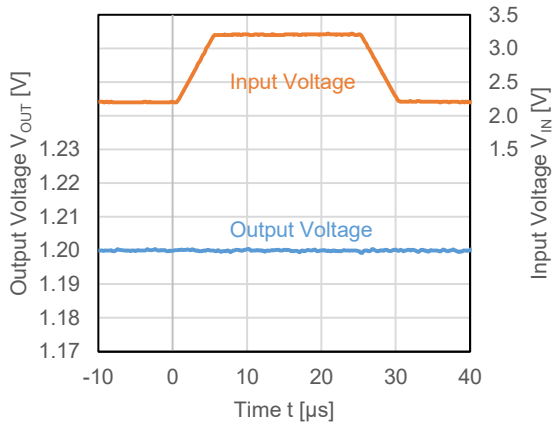


RP122x48xx, V_{IN} = 5.5 V

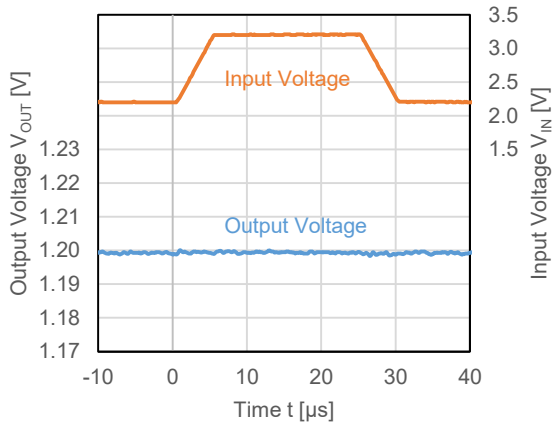


13) Input Transient Response (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF, t_R = t_F = 5 µs, Ta = 25°C)

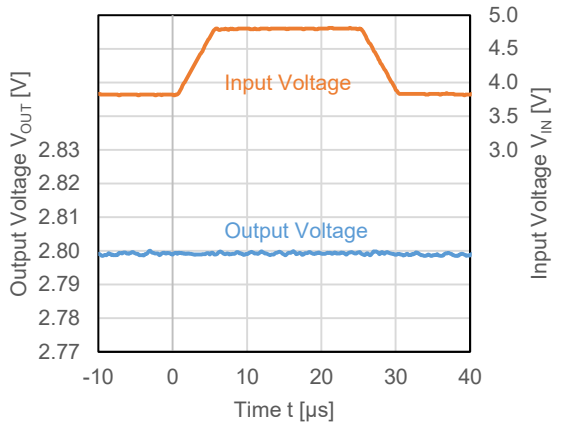
RP122x12xx, I_{OUT} = 1 mA



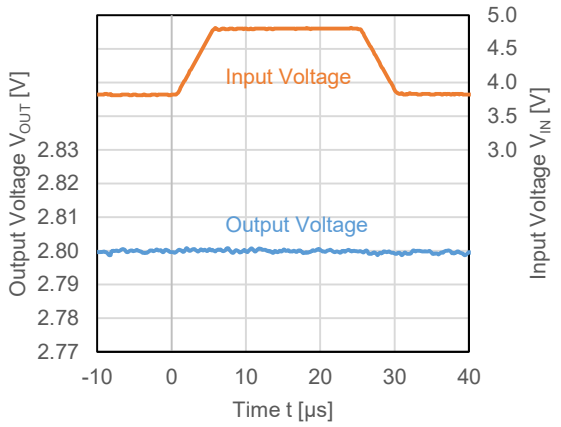
RP122x12xx, I_{OUT} = 20 mA



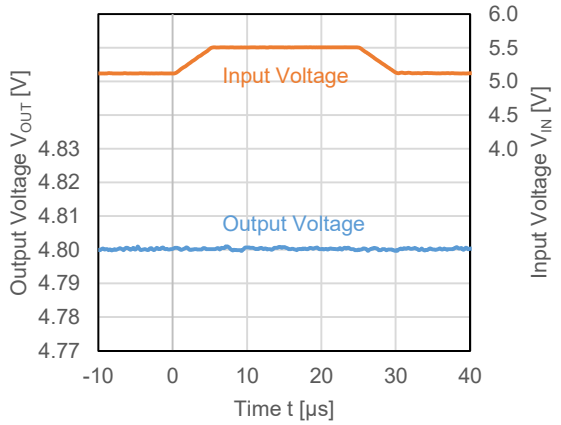
RP122x28xx, I_{OUT} = 1 mA



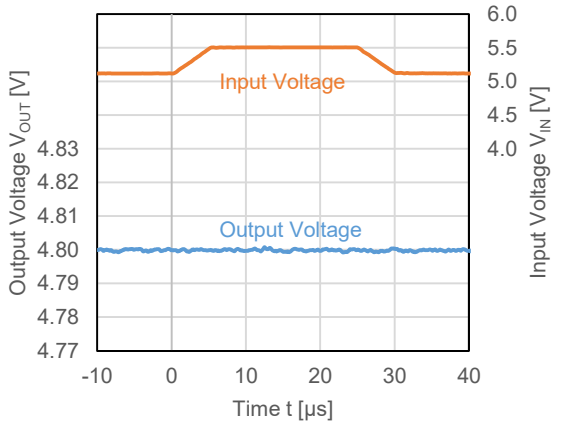
RP122x28xx, I_{OUT} = 20 mA



RP122x48xx, I_{OUT} = 1 mA

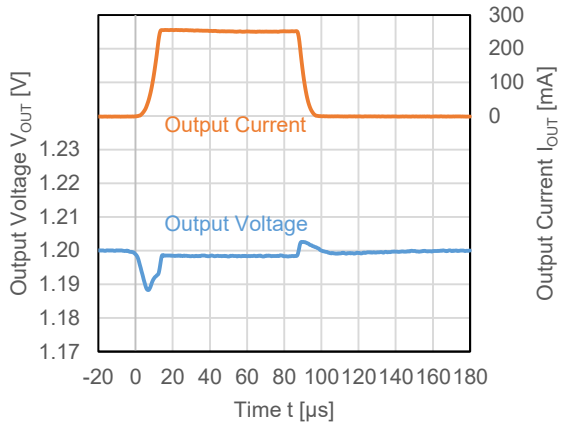


RP122x48xx, I_{OUT} = 20 mA

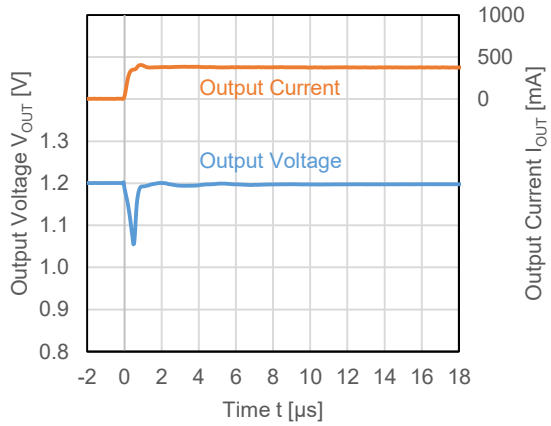


14) Load transient Response (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF, Ta = 25°C)

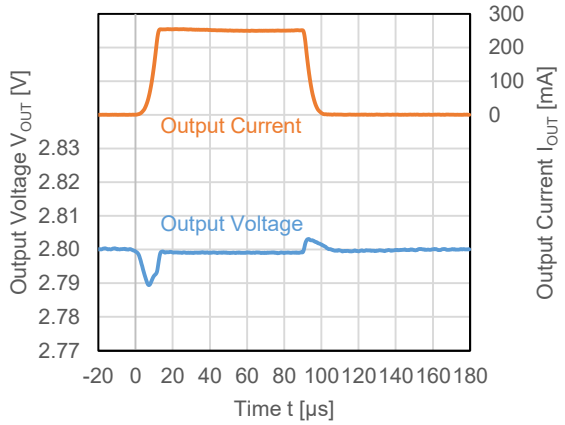
RP122x12xx, V_{IN} = 2.2 V,
I_{OUT} = 1 mA <=> 250 mA, t_R = t_F = 10 µs



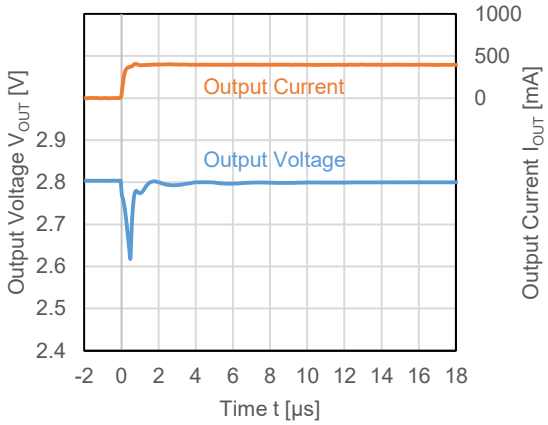
RP122x12xx, V_{IN} = 2.2 V,
I_{OUT} = 0 => 400 mA, t_R = 0.5 µs



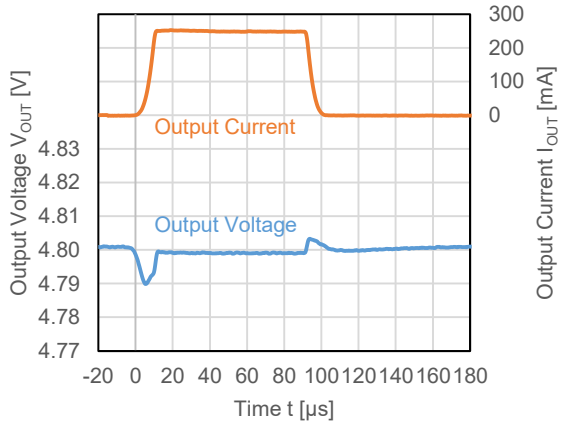
RP122x28xx, V_{IN} = 3.8 V,
I_{OUT} = 1 mA <=> 250 mA, t_R = t_F = 10 µs



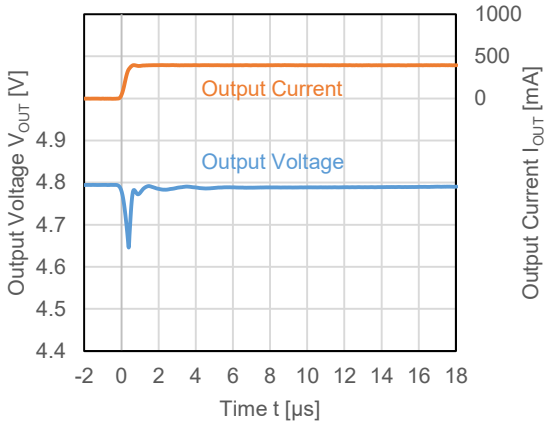
RP122x28xx, V_{IN} = 3.8 V,
I_{OUT} = 0 => 400 mA, t_R = 0.5 µs



RP122x48xx, V_{IN} = 5.5 V,
I_{OUT} = 1 mA <=> 250 mA, t_R = t_F = 10 µs

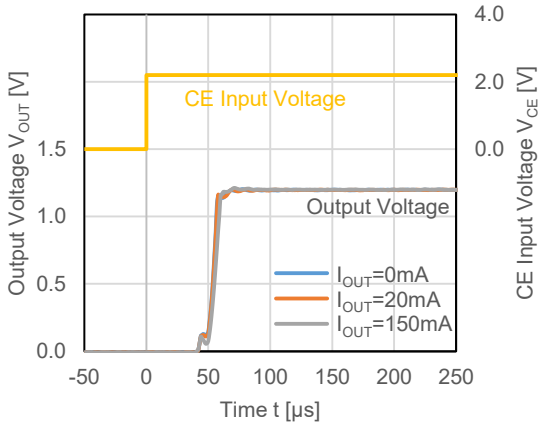


RP122x48xx, V_{IN} = 5.5 V,
I_{OUT} = 0 => 400 mA, t_R = 0.5 µs

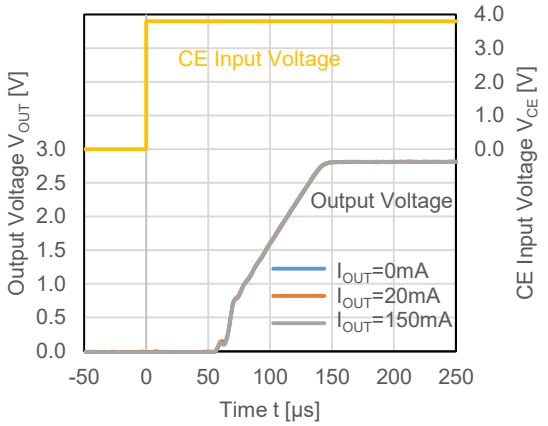


15) Turn On Speed with CE Pin (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF, Ta = 25°C)

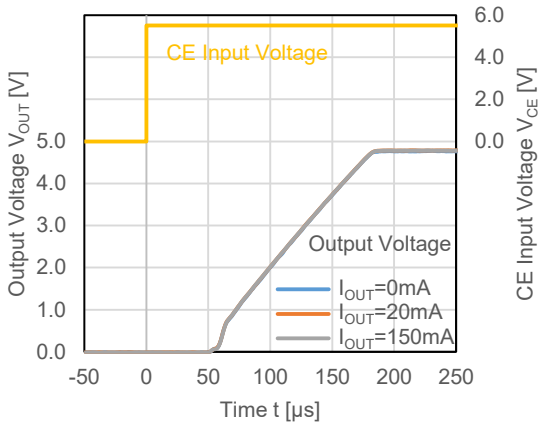
RP122x12xx, V_{IN} = 2.2 V



RP122x28xx, V_{IN} = 3.8 V

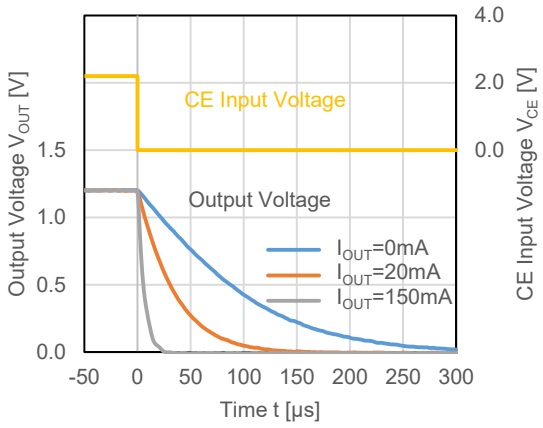


RP122x48xx, V_{IN} = 5.5V

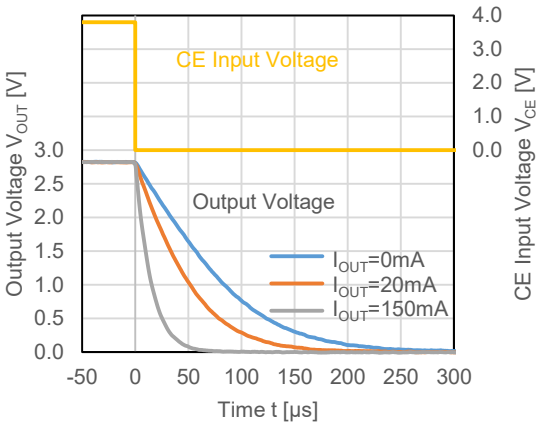


16) Turn Off Speed with CE Pin (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF, Ta = 25°C)

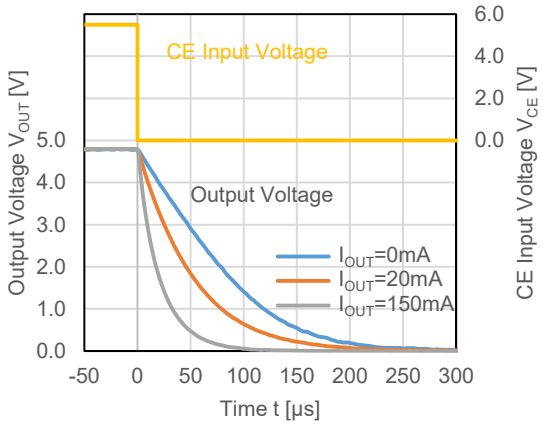
RP122x12xD, V_{IN} = 2.2 V



RP122x28xD, V_{IN} = 3.8 V

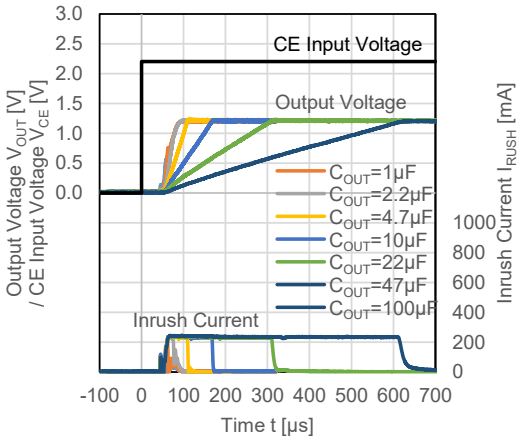


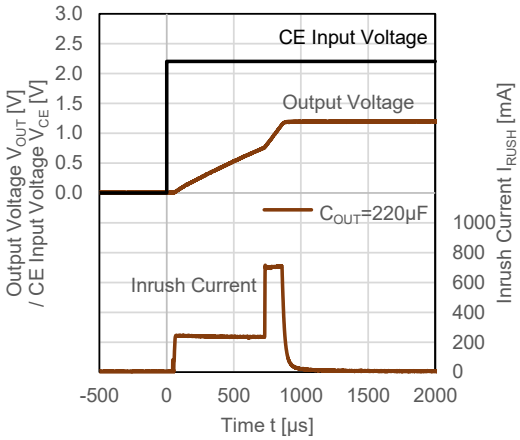
RP122x48xD, V_{IN} = 5.5V



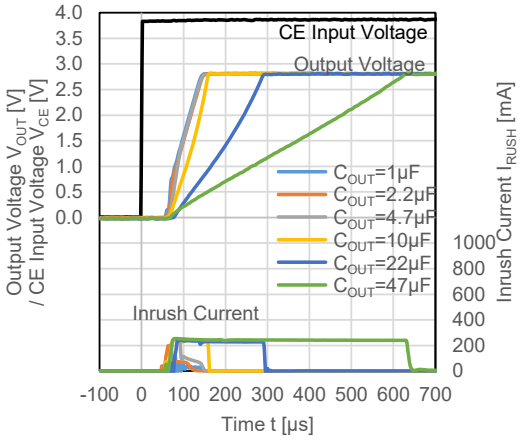
17) Inrush Current (C_{IN} = Ceramic 1.0 µF, I_{OUT} = 0 mA, Ta = 25°C)

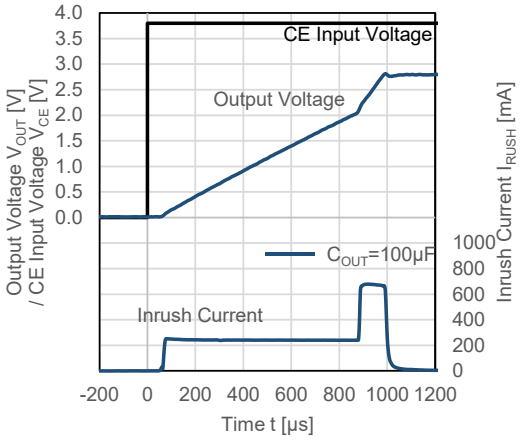
RP122x12xx, V_{IN} = 2.2 V



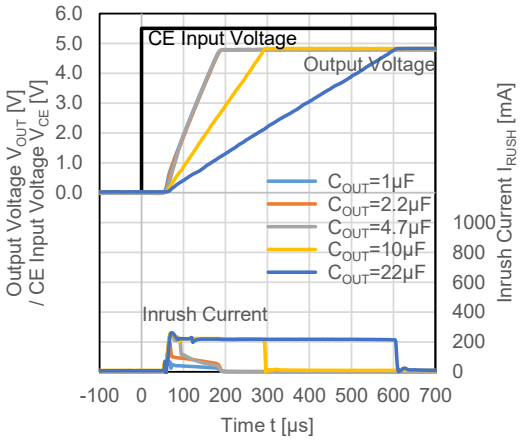


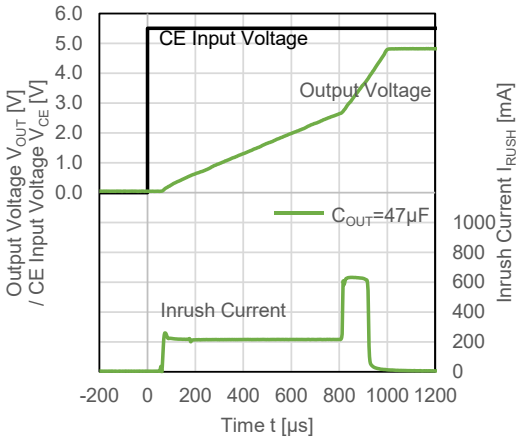
RP122x28xx, V_{IN} = 3.8 V





RP122x48xx, V_{IN} = 5.5 V





PD-WLCSP-4-P8-RP122/RP123-JE-A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-9.

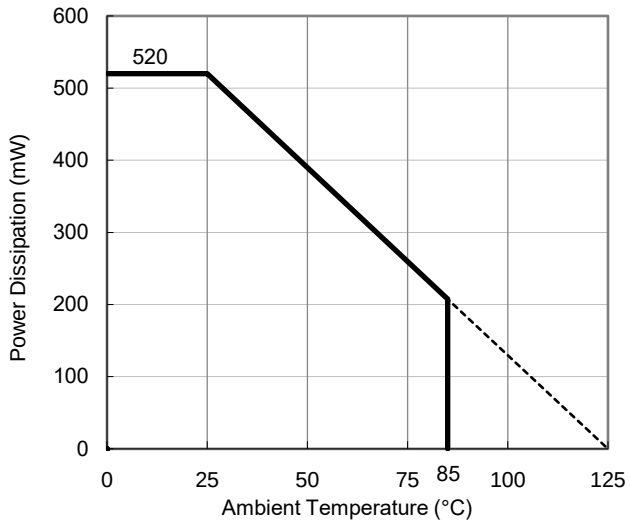
Measurement Conditions

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	101.5 mm x 114.5 mm x 1.6 mm
Copper Ratio	Outer Layer (First Layer): 60% Inner Layers (Second and Third Layers): 100% Outer Layer (Fourth Layer): 60%

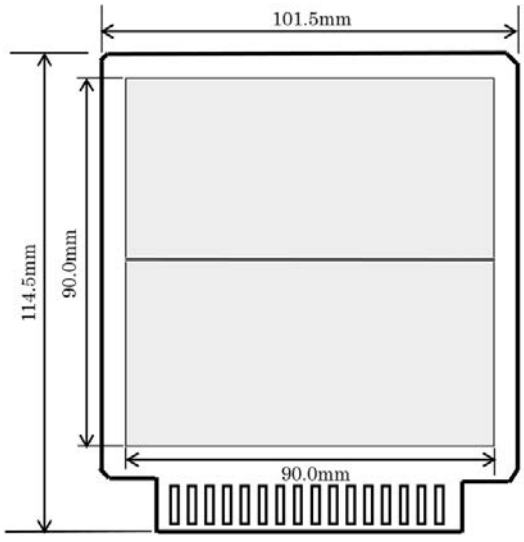
Measurement Result (Ta = 25°C, Tjmax = 125°C)

Item	Measurement Result
Power Dissipation	520 mW
Thermal Resistance (θja)	θja = 192°C/W

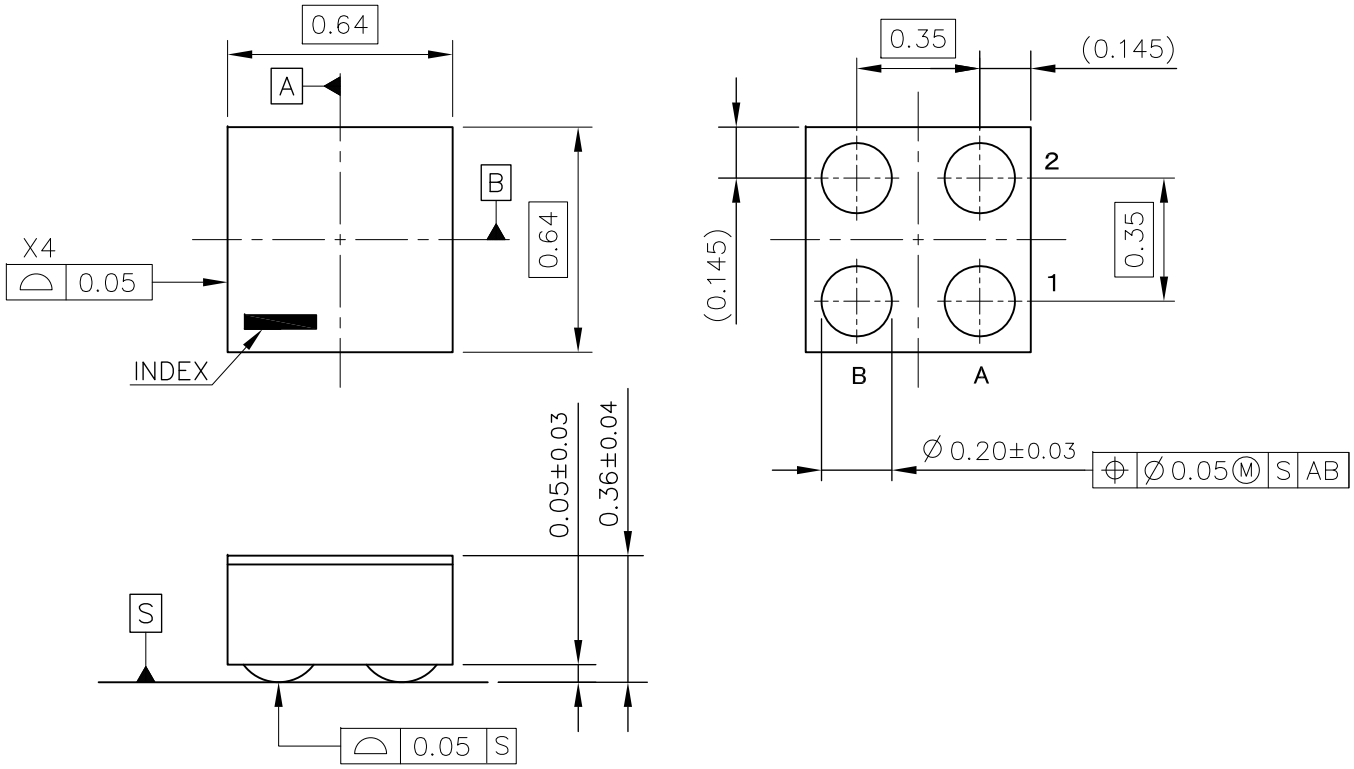
θja: Junction-to-Ambient Thermal Resistance



Power Dissipation vs. Ambient Temperature



Measurement Board Pattern



WLCSP-4-P8 Package Dimensions (Unit: mm)

PD-WLCSP-4-P12-RP122/RP123-JE-A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51.

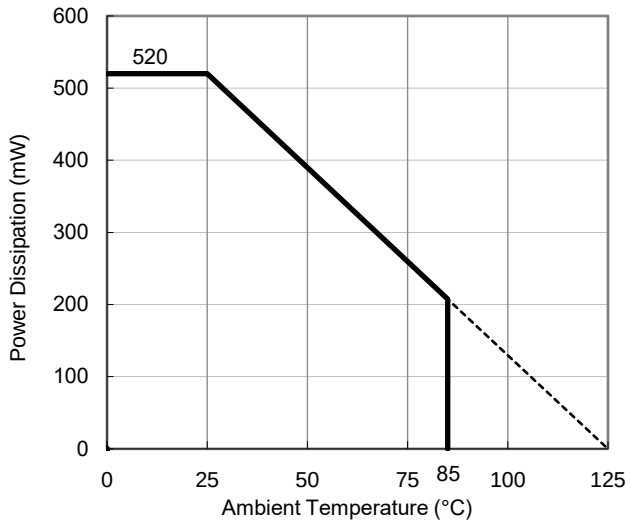
Measurement Conditions

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	101.5 mm x 114.5 mm x 1.6 mm
Copper Ratio	Outer Layer (First Layer): 60% Inner Layers (Second and Third Layers): 100% Outer Layer (Fourth Layer): 60%

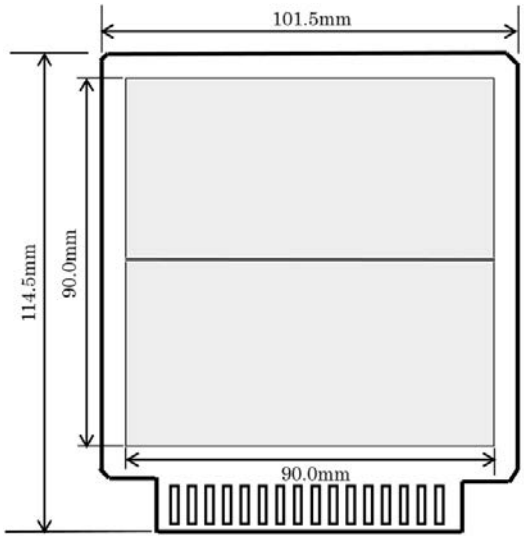
Measurement Result (Ta = 25°C, Tjmax = 125°C)

Item	Measurement Result
Power Dissipation	520 mW
Thermal Resistance (θja)	θja = 192°C/W

θja: Junction-to-Ambient Thermal Resistance

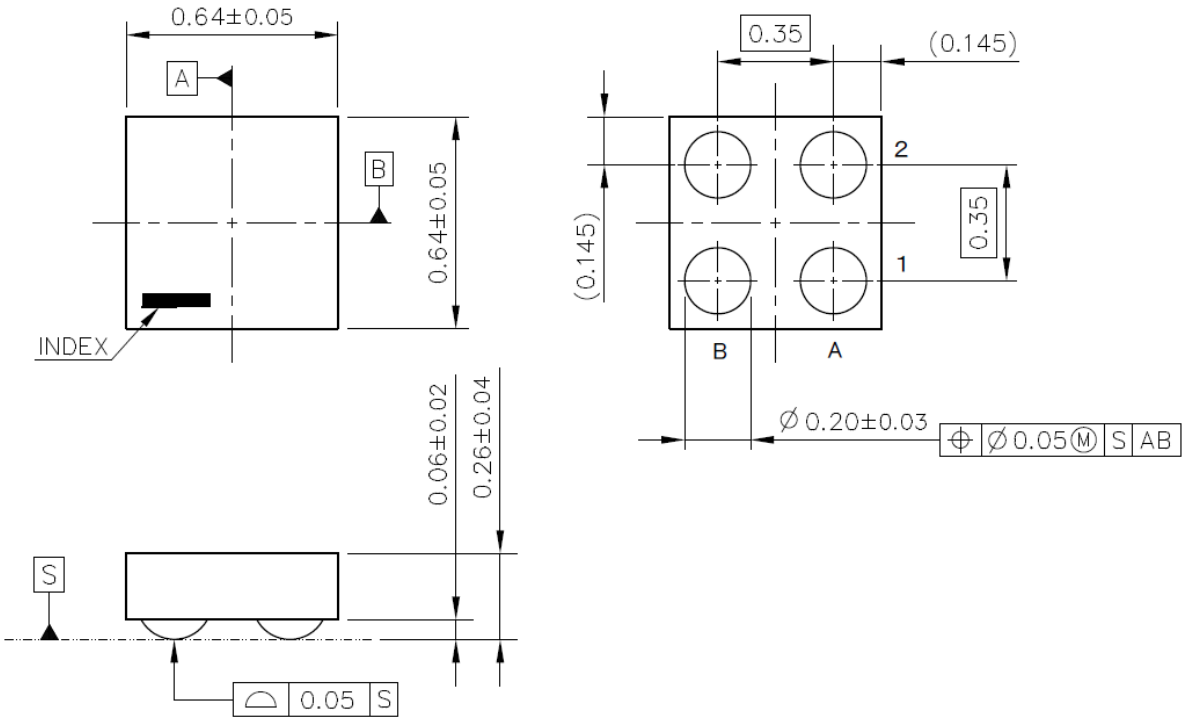


Power Dissipation vs. Ambient Temperature



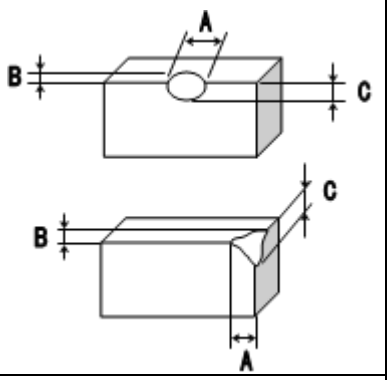
Measurement Board Pattern

DM-WLCSP-4-P12-JE-A



UNIT: mm

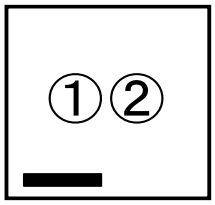
WLCSP-4-P12 Package Dimensions

No.	Inspection Items	Inspection Criteria	Figure
1	Package chipping	A≥0.2mm is rejected B≥0.2mm is rejected C≥0.2mm is rejected And, Package chipping to Si surface and to bump is rejected.	
2	Si surface chipping	A≥0.2mm is rejected B≥0.2mm is rejected C≥0.2mm is rejected But, even if A≥0.2mm, B≤0.1mm is acceptable.	
3	No bump	No bump is rejected.	
4	Marking miss	To reject incorrect marking, such as another product name marking or another lot No. marking.	
5	No marking	To reject no marking on the package.	
6	Reverse direction of marking	To reject reverse direction of marking character.	
7	Defective marking	To reject unreadable marking. (Microscope: X15/ White LED/ Viewed from vertical direction)	
8	Scratch	To reject unreadable marking character by scratch. (Microscope: X15/ White LED/ Viewed from vertical direction)	
9	Stain and Foreign material	To reject unreadable marking character by stain and foreign material. (Microscope: X15/ White LED/ Viewed from vertical direction)	

PART MARKING RP122Z

MK-RP122Z-JAEA-F

①②: Lot Number ⋯ Alphanumeric Serial Number



RP122Z (WLCSP-4-P8 / WLCSP-4-P12) Part Markings

NOTICE
There can be variation in the marking when different AOI (Automated Optical Inspection) equipment is used. In the case of recognizing the marking characteristic with AOI, please contact our sales or our distributor before attempting to use AOI.

RP122Z Part Marking List: RP122Zxx1x, RP122Zxx3x, RP122Zxx4x

Product Name	① ②	Product Name	① ②	Set Voltage
RP122Z12xB	Lot No.	RP122Z12xD	Lot No.	1.20 V
RP122Z13xB	Lot No.	RP122Z13xD	Lot No.	1.30 V
RP122Z14xB	Lot No.	RP122Z14xD	Lot No.	1.40 V
RP122Z15xB	Lot No.	RP122Z15xD	Lot No.	1.50 V
RP122Z16xB	Lot No.	RP122Z16xD	Lot No.	1.60 V
RP122Z17xB	Lot No.	RP122Z17xD	Lot No.	1.70 V
RP122Z18xB	Lot No.	RP122Z18xD	Lot No.	1.80 V
RP122Z19xB	Lot No.	RP122Z19xD	Lot No.	1.90 V
RP122Z20xB	Lot No.	RP122Z20xD	Lot No.	2.00 V
RP122Z21xB	Lot No.	RP122Z21xD	Lot No.	2.10 V
RP122Z22xB	Lot No.	RP122Z22xD	Lot No.	2.20 V
RP122Z23xB	Lot No.	RP122Z23xD	Lot No.	2.30 V
RP122Z24xB	Lot No.	RP122Z24xD	Lot No.	2.40 V
RP122Z25xB	Lot No.	RP122Z25xD	Lot No.	2.50 V
RP122Z26xB	Lot No.	RP122Z26xD	Lot No.	2.60 V
RP122Z27xB	Lot No.	RP122Z27xD	Lot No.	2.70 V
RP122Z28xB	Lot No.	RP122Z28xD	Lot No.	2.80 V
RP122Z29xB	Lot No.	RP122Z29xD	Lot No.	2.90 V
RP122Z30xB	Lot No.	RP122Z30xD	Lot No.	3.00 V
RP122Z31xB	Lot No.	RP122Z31xD	Lot No.	3.10 V
RP122Z32xB	Lot No.	RP122Z32xD	Lot No.	3.20 V
RP122Z33xB	Lot No.	RP122Z33xD	Lot No.	3.30 V
RP122Z34xB	Lot No.	RP122Z34xD	Lot No.	3.40 V
RP122Z35xB	Lot No.	RP122Z35xD	Lot No.	3.50 V
RP122Z36xB	Lot No.	RP122Z36xD	Lot No.	3.60 V
RP122Z37xB	Lot No.	RP122Z37xD	Lot No.	3.70 V
RP122Z38xB	Lot No.	RP122Z38xD	Lot No.	3.80 V
RP122Z39xB	Lot No.	RP122Z39xD	Lot No.	3.90 V
RP122Z40xB	Lot No.	RP122Z40xD	Lot No.	4.00 V
RP122Z41xB	Lot No.	RP122Z41xD	Lot No.	4.10 V
RP122Z42xB	Lot No.	RP122Z42xD	Lot No.	4.20 V
RP122Z43xB	Lot No.	RP122Z43xD	Lot No.	4.30 V
RP122Z44xB	Lot No.	RP122Z44xD	Lot No.	4.40 V
RP122Z45xB	Lot No.	RP122Z45xD	Lot No.	4.50 V
RP122Z46xB	Lot No.	RP122Z46xD	Lot No.	4.60 V
RP122Z47xB	Lot No.	RP122Z47xD	Lot No.	4.70 V
RP122Z48xB	Lot No.	RP122Z48xD	Lot No.	4.80 V
RP122Z12xB5	Lot No.	RP122Z12xD5	Lot No.	1.25 V
RP122Z18xB5	Lot No.	RP122Z18xD5	Lot No.	1.85 V
RP122Z28xB5	Lot No.	RP122Z28xD5	Lot No.	2.85 V
RP122Z45xB5	Lot No.	RP122Z45xD5	Lot No.	4.55 V
RP122Z29xB5	Lot No.	RP122Z29xD5	Lot No.	2.95 V
RP122Z31xB5	Lot No.	RP122Z31xD5	Lot No.	3.15 V
RP122Z42xB5	Lot No.	RP122Z42xD5	Lot No.	4.25 V
RP122Z30xB5	Lot No.	RP122Z30xD5	Lot No.	3.05 V

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

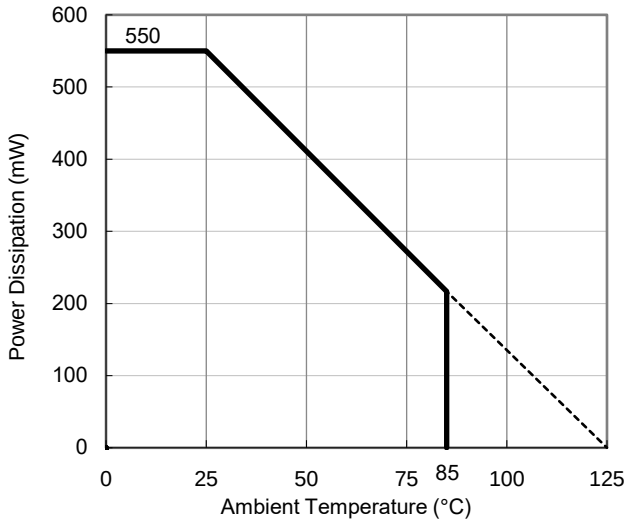
Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	ϕ 0.2 mm × 21 pcs

Measurement Result (Ta = 25°C, Tjmax = 125°C)

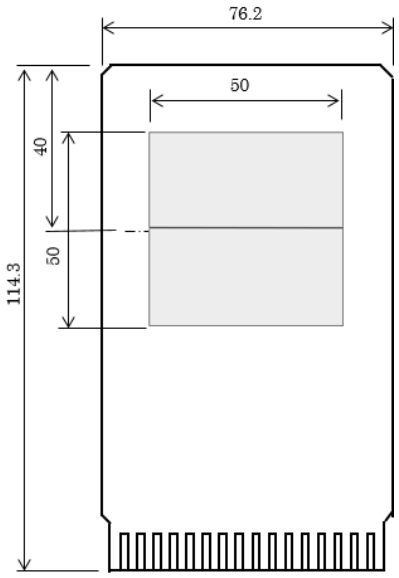
Item	Measurement Result
Power Dissipation	550 mW
Thermal Resistance (θja)	θja = 180°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 105°C/W

θja: Junction-to-Ambient Thermal Resistance

ψjt: Junction-to-Top Thermal Characterization Parameter

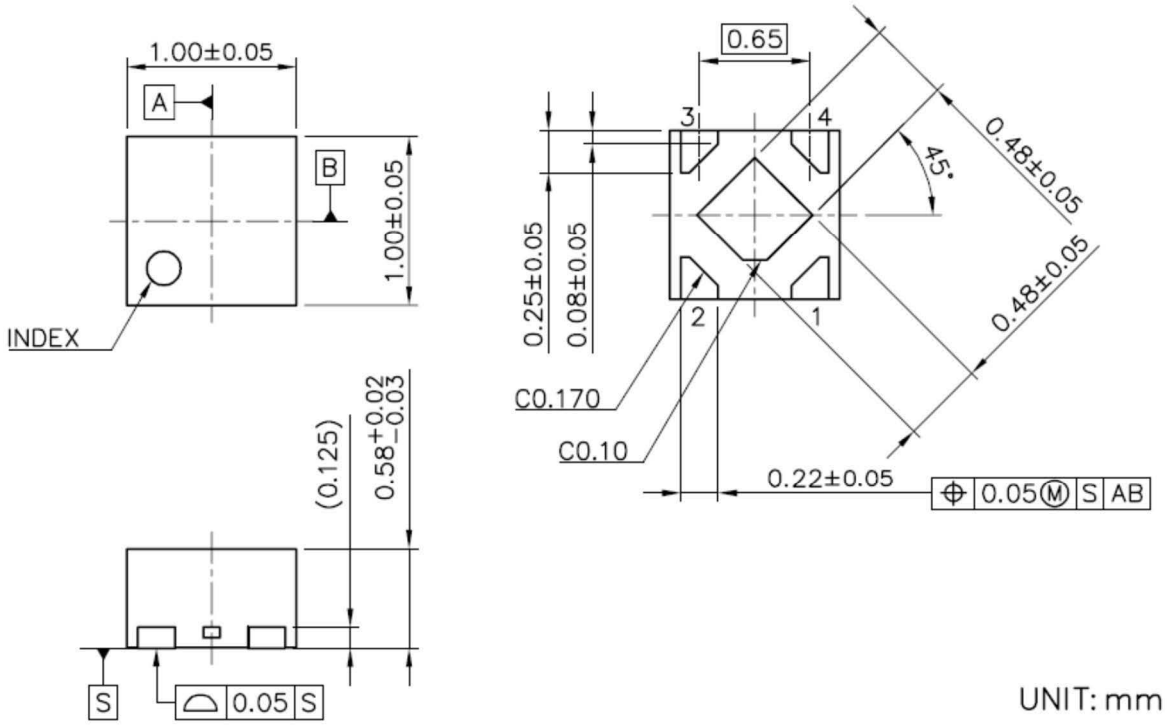


Power Dissipation vs. Ambient Temperature



Measurement Board Pattern

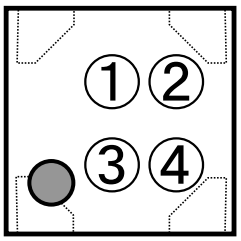
DM-DFN(PL)1010-4B-JE-C



DFN(PL)1010-4B Package Dimensions

①②: Product Code ⋯ Refer to *Part Marking List*

③④: Lot Number ⋯ Alphanumeric Serial Number



RP122K (DFN(PL)1010-4B) Part Markings

NOTICE
There can be variation in the marking when different AOI (Automated Optical Inspection) equipment is used. In the case of recognizing the marking characteristic with AOI, please contact our sales or distributor before attempting to use AOI.

RP122Kxx1x Part Marking List

Product Name	① ②	Product Name	① ②	V_{SET}
RP122K121B	L 0	RP122K121D	R 0	1.20 V
RP122K131B	L 1	RP122K131D	R 1	1.30 V
RP122K141B	L 2	RP122K141D	R 2	1.40 V
RP122K151B	L 3	RP122K151D	R 3	1.50 V
RP122K161B	L 4	RP122K161D	R 4	1.60 V
RP122K171B	L 5	RP122K171D	R 5	1.70 V
RP122K181B	L 6	RP122K181D	R 6	1.80 V
RP122K191B	L 7	RP122K191D	R 7	1.90 V
RP122K201B	L 8	RP122K201D	R 8	2.00 V
RP122K211B	L 9	RP122K211D	R 9	2.10 V
RP122K221B	M 0	RP122K221D	S 0	2.20 V
RP122K231B	M 1	RP122K231D	S 1	2.30 V
RP122K241B	M 2	RP122K241D	S 2	2.40 V
RP122K251B	M 3	RP122K251D	S 3	2.50 V
RP122K261B	M 4	RP122K261D	S 4	2.60 V
RP122K271B	M 5	RP122K271D	S 5	2.70 V
RP122K281B	M 6	RP122K281D	S 6	2.80 V
RP122K291B	M 7	RP122K291D	S 7	2.90 V
RP122K301B	M 8	RP122K301D	S 8	3.00 V
RP122K311B	M 9	RP122K311D	S 9	3.10 V
RP122K321B	N 0	RP122K321D	T 0	3.20 V
RP122K331B	N 1	RP122K331D	T 1	3.30 V
RP122K341B	N 2	RP122K341D	T 2	3.40 V
RP122K351B	N 3	RP122K351D	T 3	3.50 V
RP122K361B	N 4	RP122K361D	T 4	3.60 V
RP122K371B	N 5	RP122K371D	T 5	3.70 V
RP122K381B	N 6	RP122K381D	T 6	3.80 V
RP122K391B	N 7	RP122K391D	T 7	3.90 V
RP122K401B	N 8	RP122K401D	T 8	4.00 V
RP122K411B	N 9	RP122K411D	T 9	4.10 V
RP122K421B	P 0	RP122K421D	U 0	4.20 V
RP122K431B	P 1	RP122K431D	U 1	4.30 V
RP122K441B	P 2	RP122K441D	U 2	4.40 V
RP122K451B	P 3	RP122K451D	U 3	4.50 V
RP122K461B	P 4	RP122K461D	U 4	4.60 V
RP122K471B	P 5	RP122K471D	U 5	4.70 V
RP122K481B	P 6	RP122K481D	U 6	4.80 V
RP122K121B5	P 7	RP122K121D5	U 7	1.25 V
RP122K181B5	P 8	RP122K181D5	U 8	1.85 V
RP122K281B5	P 9	RP122K281D5	U 9	2.85 V
RP122K451B5	W 0	RP122K451D5	V 0	4.55 V
RP122K291B5	W 1	RP122K291D5	V 1	2.95 V
RP122K311B5	W 2	RP122K311D5	V 2	3.15 V
RP122K421B5	W 3	RP122K421D5	V 3	4.25 V
RP122K301B5	W 4	RP122K301D5	V 4	3.05 V
RP122K351B5	W 5	RP122K351D5	V 5	3.55 V

PD-SOT-23-5-(85125)-JE-B

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

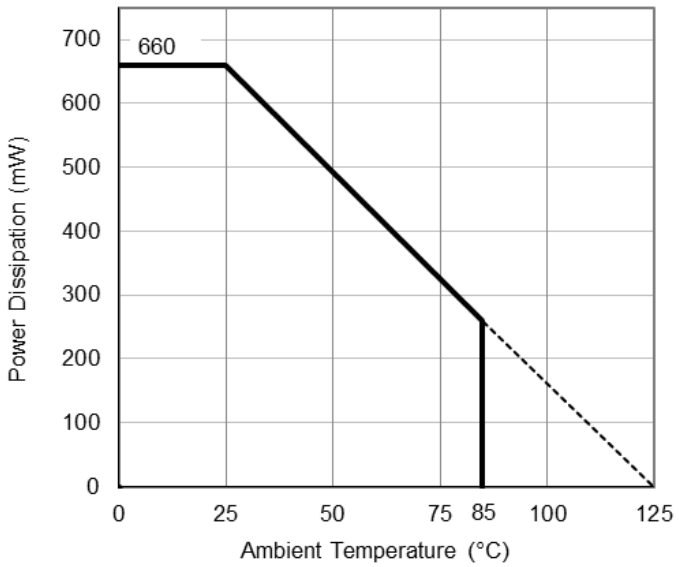
Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	ϕ 0.3 mm × 7 pcs

Measurement Result (Ta = 25°C, Tjmax = 125°C)

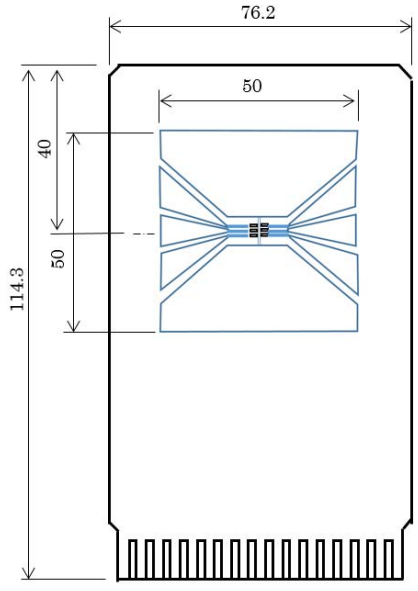
Item	Measurement Result
Power Dissipation	660 mW
Thermal Resistance (θja)	θja = 150°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 51°C/W

θja: Junction-to-Ambient Thermal Resistance

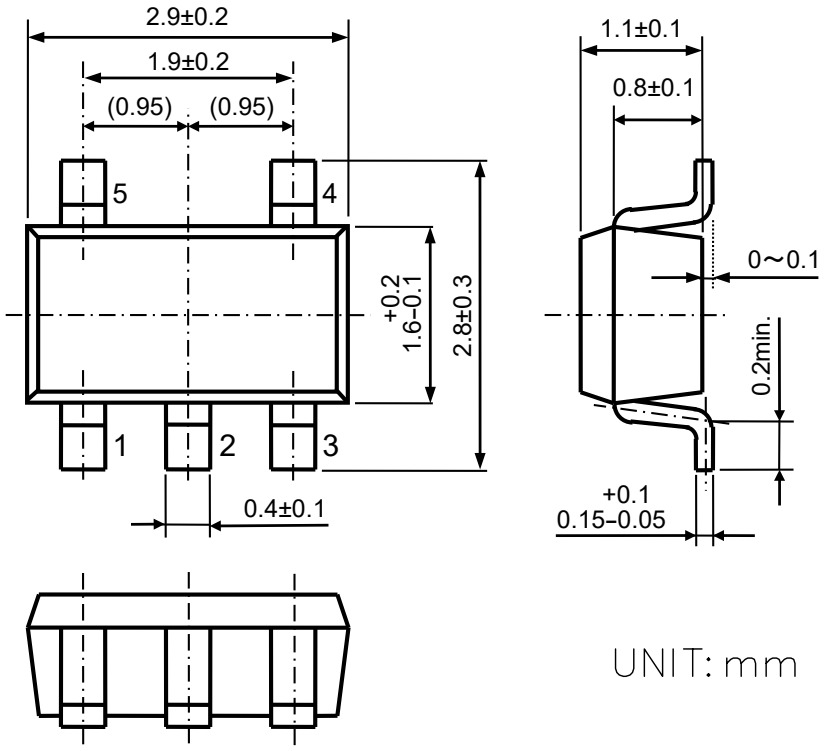
ψjt: Junction-to-Top Thermal Characterization Parameter



Power Dissipation vs. Ambient Temperature



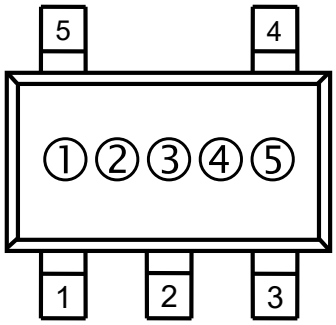
Measurement Board Pattern



SOT-23-5 Package Dimensions

①②③: Product Code ⋯ Refer to *Part Marking List*

④⑤: Lot Number ⋯ Alphanumeric Serial Number



RP122N (SOT-23-5) Part Markings

NOTICE
There can be variation in the marking when different AOI (Automated Optical Inspection) equipment is used. In the case of recognizing the marking characteristic with AOI, please contact our sales or our distributor before attempting to use AOI.

RP122Nxx1x Part Marking List

Product Name	①	②	③	Product Name	①	②	③	V_{SET}
RP122N121B	1	A	0	RP122N121D	3	A	0	1.20 V
RP122N131B	1	A	1	RP122N131D	3	A	1	1.30 V
RP122N141B	1	A	2	RP122N141D	3	A	2	1.40 V
RP122N151B	1	A	3	RP122N151D	3	A	3	1.50 V
RP122N161B	1	A	4	RP122N161D	3	A	4	1.60 V
RP122N171B	1	A	5	RP122N171D	3	A	5	1.70 V
RP122N181B	1	A	6	RP122N181D	3	A	6	1.80 V
RP122N191B	1	A	7	RP122N191D	3	A	7	1.90 V
RP122N201B	1	A	8	RP122N201D	3	A	8	2.00 V
RP122N211B	1	A	9	RP122N211D	3	A	9	2.10 V
RP122N221B	1	B	0	RP122N221D	3	B	0	2.20 V
RP122N231B	1	B	1	RP122N231D	3	B	1	2.30 V
RP122N241B	1	B	2	RP122N241D	3	B	2	2.40 V
RP122N251B	1	B	3	RP122N251D	3	B	3	2.50 V
RP122N261B	1	B	4	RP122N261D	3	B	4	2.60 V
RP122N271B	1	B	5	RP122N271D	3	B	5	2.70 V
RP122N281B	1	B	6	RP122N281D	3	B	6	2.80 V
RP122N291B	1	B	7	RP122N291D	3	B	7	2.90 V
RP122N301B	1	B	8	RP122N301D	3	B	8	3.00 V
RP122N311B	1	B	9	RP122N311D	3	B	9	3.10 V
RP122N321B	1	C	0	RP122N321D	3	C	0	3.20 V
RP122N331B	1	C	1	RP122N331D	3	C	1	3.30 V
RP122N341B	1	C	2	RP122N341D	3	C	2	3.40 V
RP122N351B	1	C	3	RP122N351D	3	C	3	3.50 V
RP122N361B	1	C	4	RP122N361D	3	C	4	3.60 V
RP122N371B	1	C	5	RP122N371D	3	C	5	3.70 V
RP122N381B	1	C	6	RP122N381D	3	C	6	3.80 V
RP122N391B	1	C	7	RP122N391D	3	C	7	3.90 V
RP122N401B	1	C	8	RP122N401D	3	C	8	4.00 V
RP122N411B	1	C	9	RP122N411D	3	C	9	4.10 V
RP122N421B	1	D	0	RP122N421D	3	D	0	4.20 V
RP122N431B	1	D	1	RP122N431D	3	D	1	4.30 V
RP122N441B	1	D	2	RP122N441D	3	D	2	4.40 V
RP122N451B	1	D	3	RP122N451D	3	D	3	4.50 V
RP122N461B	1	D	4	RP122N461D	3	D	4	4.60 V
RP122N471B	1	D	5	RP122N471D	3	D	5	4.70 V
RP122N481B	1	D	6	RP122N481D	3	D	6	4.80 V
RP122N121B5	2	A	0	RP122N121D5	4	A	0	1.25 V
RP122N181B5	2	A	1	RP122N181D5	4	A	1	1.85 V
RP122N281B5	2	A	2	RP122N281D5	4	A	2	2.85 V
RP122N451B5	2	A	3	RP122N451D5	4	A	3	4.55 V
RP122N291B5	2	A	4	RP122N291D5	4	A	4	2.95 V
RP122N311B5	2	A	5	RP122N311D5	4	A	5	3.15 V
RP122N421B5	2	A	6	RP122N421D5	4	A	6	4.25 V
RP122N301B5	2	A	7	RP122N301D5	4	A	7	3.05 V

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    - Various Safety Devices
    - Traffic control system
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6. We are making our continuous effort to improve the quality and reliability of our products, but semiconductor products are likely to fail with certain probability. In order to prevent any injury to persons or damages to property resulting from such failure, customers should be careful enough to incorporate safety measures in their design, such as redundancy feature, fire containment feature and fail-safe feature. We do not assume any liability or responsibility for any loss or damage arising from misuse or inappropriate use of the products.
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8. Quality Warranty
    8-1. Quality Warranty Period
    In the case of a product purchased through an authorized distributor or directly from us, the warranty period for this product shall be one (1) year after delivery to your company. For defective products that occurred during this period, we will take the quality warranty measures described in section 8-2. However, if there is an agreement on the warranty period in the basic transaction agreement, quality assurance agreement, delivery specifications, etc., it shall be followed.
    8-2. Quality Warranty Remedies
    When it has been proved defective due to manufacturing factors as a result of defect analysis by us, we will either deliver a substitute for the defective product or refund the purchase price of the defective product.
    Note that such delivery or refund is sole and exclusive remedies to your company for the defective product.
    8-3. Remedies after Quality Warranty Period
    With respect to any defect of this product found after the quality warranty period, the defect will be analyzed by us. On the basis of the defect analysis results, the scope and amounts of damage shall be determined by mutual agreement of both parties. Then we will deal with upper limit in Section 8-2. This provision is not intended to limit any legal rights of your company.
9. Anti-radiation design is not implemented in the products described in this document.
10. The X-ray exposure can influence functions and characteristics of the products. Confirm the product functions and characteristics in the evaluation stage.
11. WLCSP products should be used in light shielded environments. The light exposure can influence functions and characteristics of the products under operation or storage.
12. Warning for handling Gallium and Arsenic (GaAs) products (Applying to GaAs MMIC, Photo Reflector). These products use Gallium (Ga) and Arsenic (As) which are specified as poisonous chemicals by law. For the prevention of a hazard, do not burn, destroy, or process chemically to make them as gas or power. When the product is disposed of, please follow the related regulation and do not mix this with general industrial waste or household waste.
13. Please contact our sales representatives should you have any questions or comments concerning the products or the technical information.

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